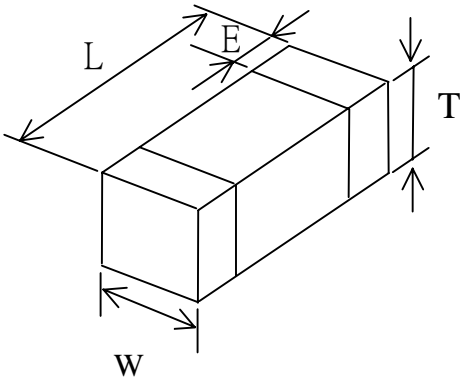


Multilayer chip inductor 1608 (0603) series

PRODUCT DETAIL

Electrical Characteristics			Test Instruments
L	uH (Ref. Page 2~3)	TEST FREQ: (Ref. Page 2~3)	<ul style="list-style-type: none"> •HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHM METER •Agilent 8720ES S-PARA METER NETWORK ANALYZER •HP6632B SYSTEM DC POWER SUPPLY
Q	(Ref. Page 2~3)	MHz	
SRF	MHz (Ref. Page 2~3)	TEST LEVEL: 100mV	
DCR	Ω (Ref. Page 2~3)		
IDC	mA (Ref. Page 2~3)		

SHAPES AND DIMENSIONS



Unit: mm

TYPE	1608E1
L	1.6±0.15
W	0.8±0.15
T	0.8±0.15
E	0.3±0.20

Multilayer chip inductor

▪PART NUMBER AND CHARACTERISTICS TABLE

BCCL-1608E1 Series

Part No.	Thickness (mm)	Inductance & Tolerance (μ H)	Q (min)	Freq. (MHz)	S. R. F (MHz) Min	DCR(Ω) (Max.)	Rated Current (mA)
BCCL-1608E1-R047M	0.8 ± 0.15	0.047±20%	10	50	260	0.25	50
BCCL-1608E1-R056M	0.8 ± 0.15	0.056±20%	10	50	255	0.25	50
BCCL-1608E1-R068M	0.8 ± 0.15	0.068±20%	10	50	250	0.25	50
BCCL-1608E1-R082M	0.8 ± 0.15	0.082±20%	10	50	245	0.25	50
BCCL-1608E1-R10K	0.8 ± 0.15	0.10 ± 10%	15	25	240	0.50	50
BCCL-1608E1-R12K	0.8 ± 0.15	0.12 ± 10%	15	25	235	0.50	50
BCCL-1608E1-R15K	0.8 ± 0.15	0.15 ± 10%	15	25	205	0.60	50
BCCL-1608E1-R18K	0.8 ± 0.15	0.18 ± 10%	15	25	190	0.60	50
BCCL-1608E1-R22K	0.8 ± 0.15	0.22 ± 10%	15	25	170	0.80	50
BCCL-1608E1-R27K	0.8 ± 0.15	0.27 ± 10%	15	25	155	0.80	50
BCCL-1608E1-R33K	0.8 ± 0.15	0.33 ± 10%	15	25	140	0.80	35
BCCL-1608E1-R39K	0.8 ± 0.15	0.39 ± 10%	15	25	125	1.00	35
BCCL-1608E1-R47K	0.8 ± 0.15	0.47 ± 10%	15	25	120	1.00	35
BCCL-1608E1-R56K	0.8 ± 0.15	0.56 ± 10%	15	25	110	1.55	35
BCCL-1608E1-R68K	0.8 ± 0.15	0.68 ± 10%	15	25	100	1.70	35
BCCL-1608E1-R82K	0.8 ± 0.15	0.82 ± 10%	15	25	95	2.10	35
BCCL-1608E1-1R0K	0.8 ± 0.15	1.0 ± 10%	35	10	85	0.60	25
BCCL-1608E1-1R2K	0.8 ± 0.15	1.2 ± 10%	35	10	70	0.80	25
BCCL-1608E1-1R5K	0.8 ± 0.15	1.5 ± 10%	35	10	65	0.80	25
BCCL-1608E1-1R8K	0.8 ± 0.15	1.8 ± 10%	35	10	60	0.80	25
BCCL-1608E1-2R2K	0.8 ± 0.15	2.2 ± 10%	35	10	55	1.00	15
BCCL-1608E1-2R7K	0.8 ± 0.15	2.7 ± 10%	35	10	50	1.35	15
BCCL-1608E1-3R3K	0.8 ± 0.15	3.3 ± 10%	35	10	45	1.40	15
BCCL-1608E1-4R7K	0.8 ± 0.15	4.7 ± 10%	40	10	40	1.80	15

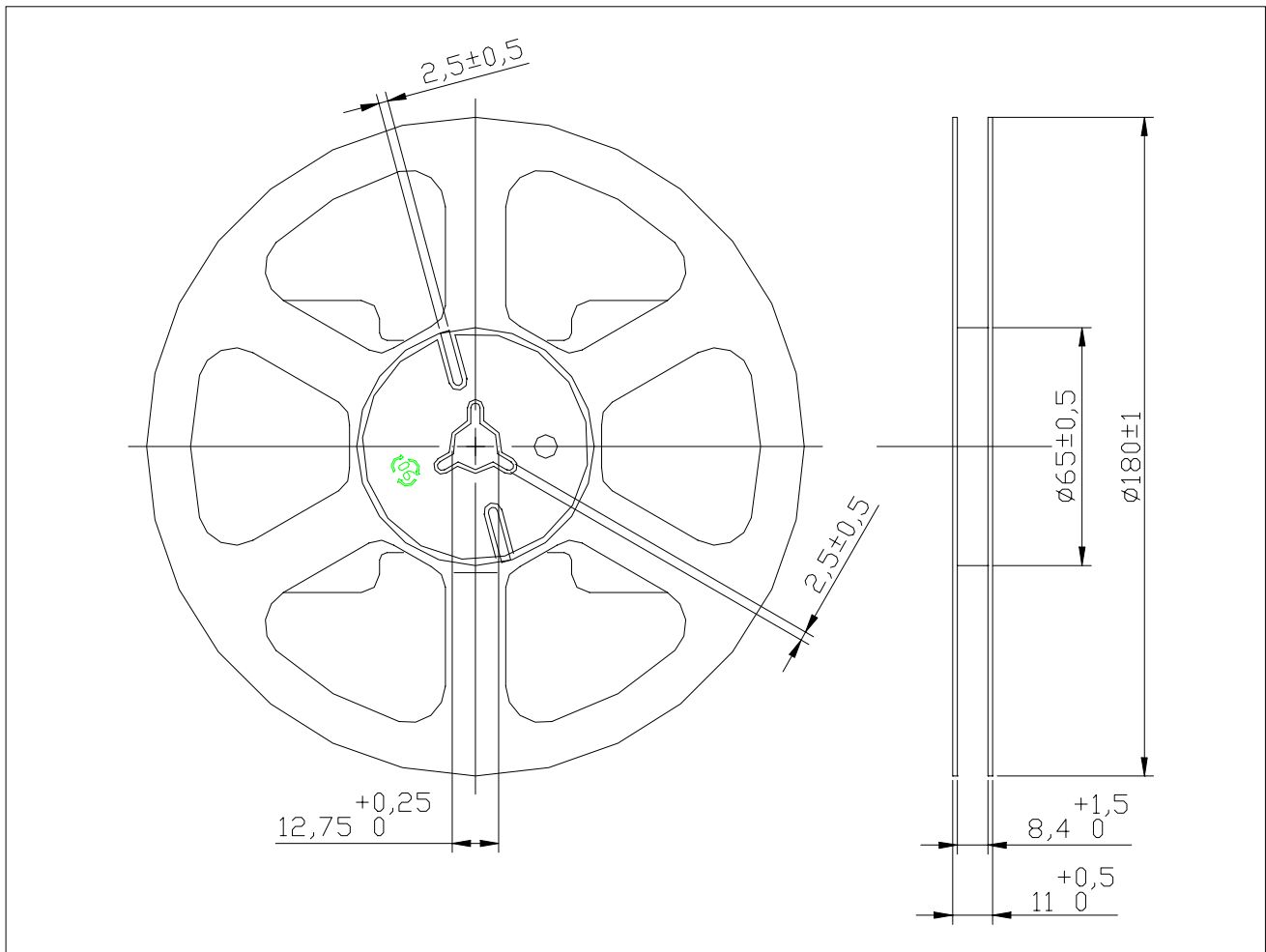
Specification For Approval

AXIS POWER 經軸電子

Part No.	Thickness (mm)	Inductance & Tolerance (μ H)	Q (min)	Freq. (MHz)	S. R. F (MHz) Min	DCR(Ω) (Max.)	Rated Current (mA)
BCCL-1608E1-10RK	0.8 \pm 0.15	10.0 \pm 10%	30	2	17	1.85	3

REEL DIMENSIONS

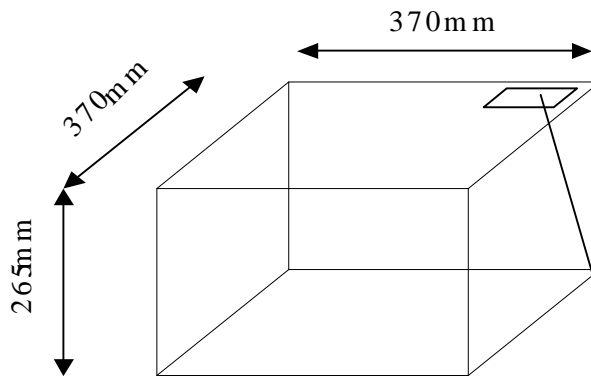
Unit: mm



Reel Packaging Quantity									
PART SIZE		1005	1608	201209	201212	3216	3225	4516	4532
7" REEL	Qty. (pcs)	10,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000
13" REEL		NA	NA	10,000	10,000	10,000	5,000	5,000	2,500
BULK		20,000	20,000	20,000	20,000	20,000	10,000	10,000	10,000

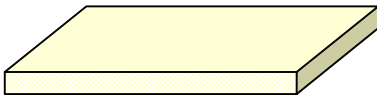
PACKING

Carton size	L*W*H (mm)	Loading Quantity 7" (reels)	Loading quantity 13" (reels)
L	370*370*265	40	12
M	370*370*133	20	5
S	370*200*133	20	-

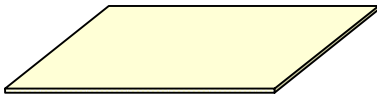


1. Put taped reel in an anti-static bag.
2. Put desiccant in an anti-static bag, and seal the anti-static bag by heat pressing.
3. Put the styrofoam in the bottom and around the box.
4. Put 4 reels which was packed as step 2 in one layer.
5. Then, put the stiffener on the top of those four reels as an isolation on between layer and layer.
6. Repeat step 4 and 5 until there is 10 layers in one box.
7. Before sealing the box, put the styrofoam on the top. Then, using adhesive tape to seal the box.
8. Stick the shipment label on the top of the box.
9. Recommended storage temperature:
Temp : 40°C Max.
Humidity : 70% RH Max.

LABEL



Styrofoam: × 6 (350mm*350mm*15mm)



Stiffener: × 10 (340*340mm)



Taped reel + desiccant + anti-static bag: × 40

RELIABILITY AND TEST CONDITION

Stress	Performance	Test Condition
Leaching	The chip should not crack ; More than 90% of the terminal electrode should be covered with solder , free from defects, chip body should not exposed.	1.Solder: Alpha Sn100 2.Solder Temp: 260 ±5 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solderability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short , open ,...etc defect symptom	1.Solder: M705-GRN360-K2-V Sn96.5/Ag3/Cu0.5 2.General:135/135/195/235 3.100% TIN:155/155/220/265
Solderability 2	More than 90% of the terminal electrode should be covered with new solder	1.Solder: Alpha Sn100 2.Solder Temp.:230 ±5 3.Flux: Rosin 4.Dip time: 4±1 sec
Terminal Strength	The terminal electrode should not break off nor the ferrite damaged	100505>0.2kgt , 160808>0.3kgt , 201209>0.6kgt , 201212>0.6kgt , 321611>1.0kgt , 322513>1.0kgt , 451616>1.0kgt , 453215>1.5kgt , BCCBA3216>1.2kgt ; pulling time:30 ±5 sec
Bending Strength	The ferrite should not be damaged by force applied on the right	100505>0.2kgf , 160808>0.3kgf , 201209>1.0kgf , 201212>1.0kgf , 321611>2.0kgf , 322513>2.5kgf , 451616>2.5kgf , 453215>2.5kgf , BCCBA3216>2.0kgf
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1.At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be	1.Temperature:-40 ~ 85 For 30 minutes each 2.Cycle: 100 cycles 3.Measurement: At ambient temperature 24 hours After test completion

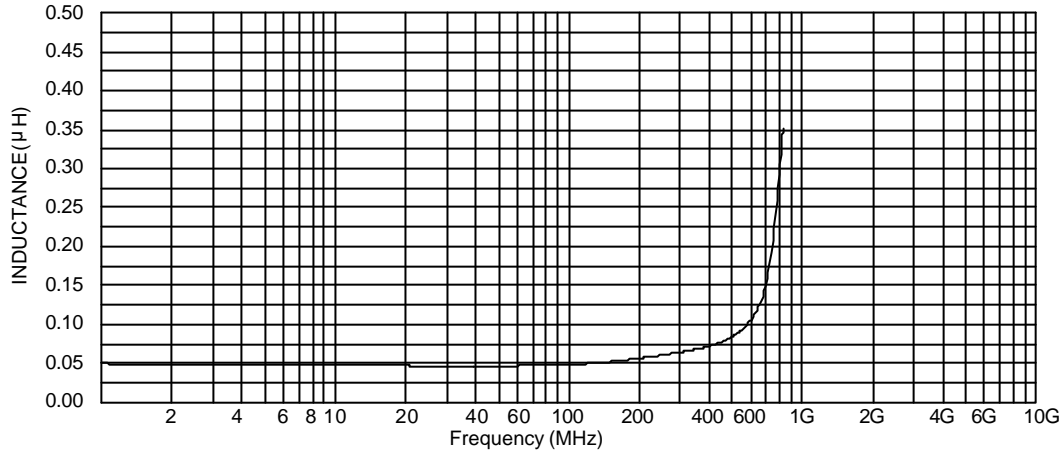
	within $\pm 20\%$ of the initial value	
Temperature Cycling	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1. Temperature:-40~125 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours After test completion
Biased Humidity	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1.Temperature: 40 2.Humidity: 85 % RH 3.Applied current: Full rated current 4.Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours After test completion
Rated Current	<ol style="list-style-type: none"> 1.BCCB /BCCL / BCCLH product Surface temperature below room temperature plus 10 2.High current DC power (ES) product surface temp. below room temperature plus 40 	<ol style="list-style-type: none"> 1.At ambient temperature & humidity 2.Testing time:5 minutes (under full rated current)

BCCL-1608E1-R047M

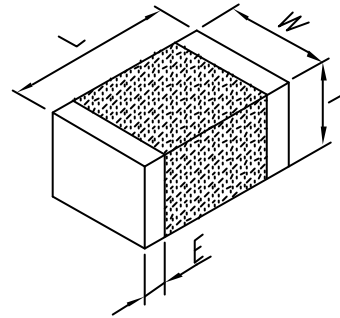
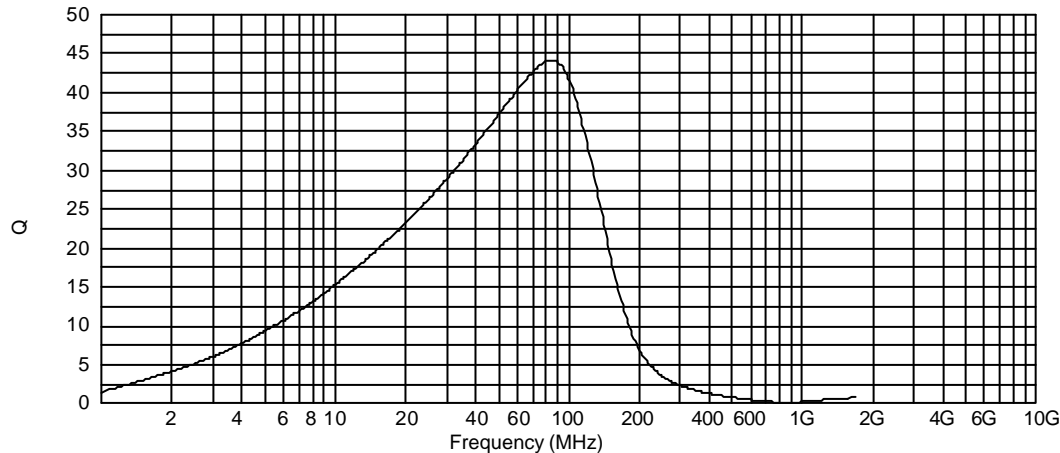
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.047	10	0.25	260	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

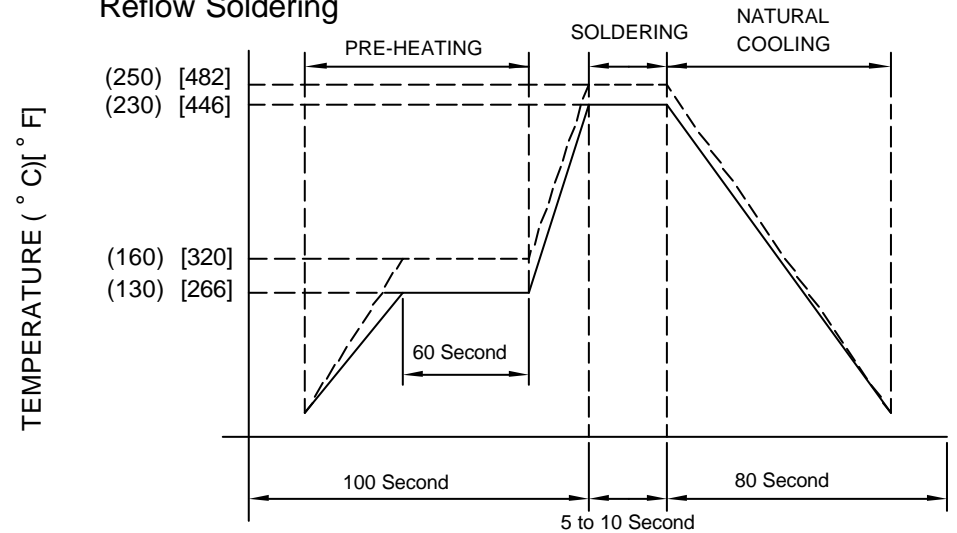
- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

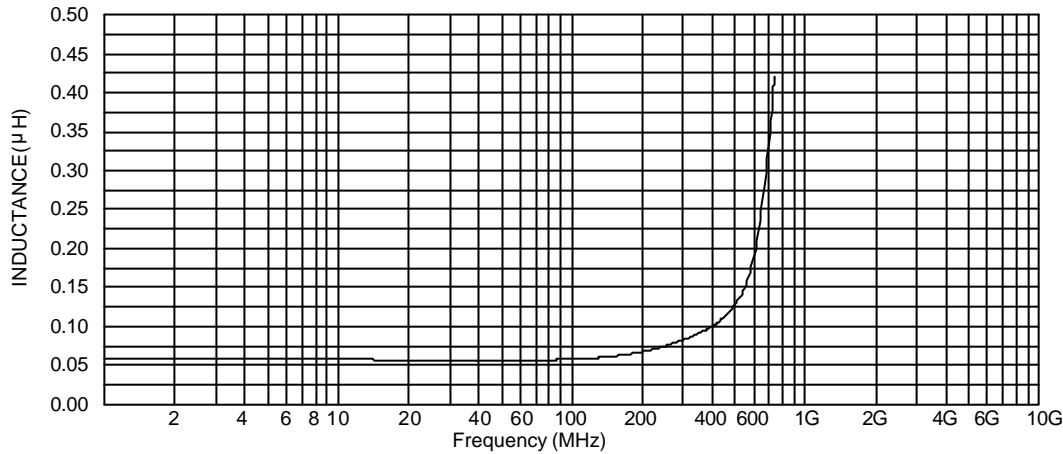
For lead free solder - - - - -

BCCL-1608E1-R056M

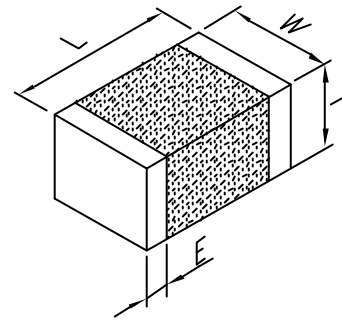
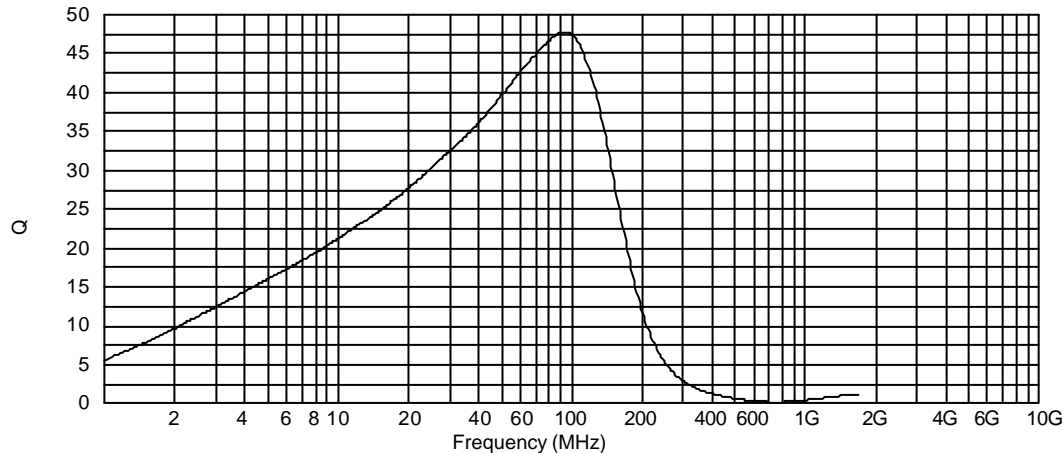
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.056	10	0.25	255	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

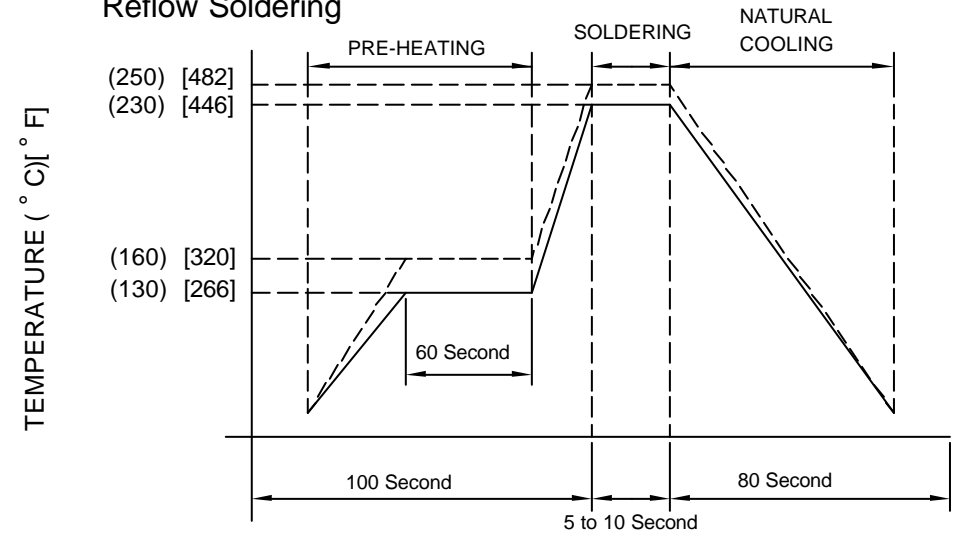
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

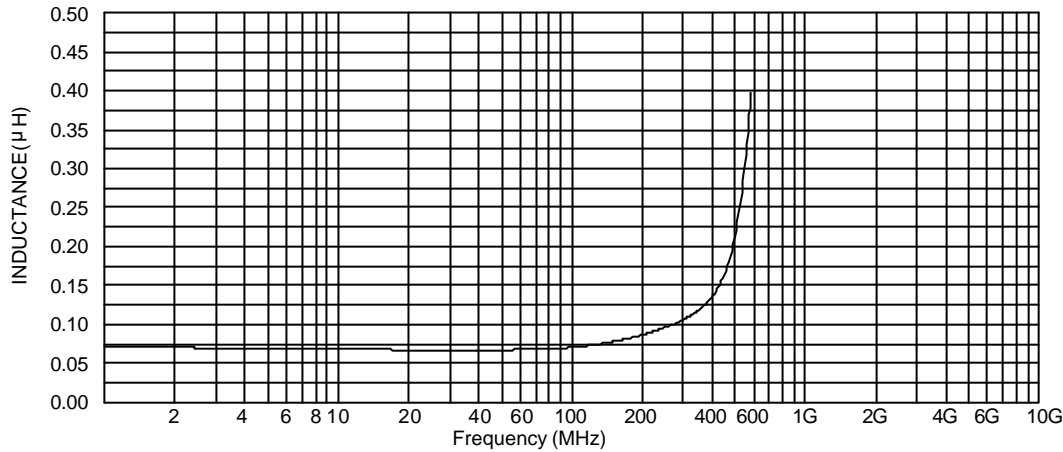
For lead free solder - - - - -

BCCL-1608E1-R068M

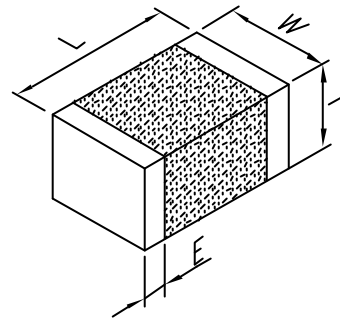
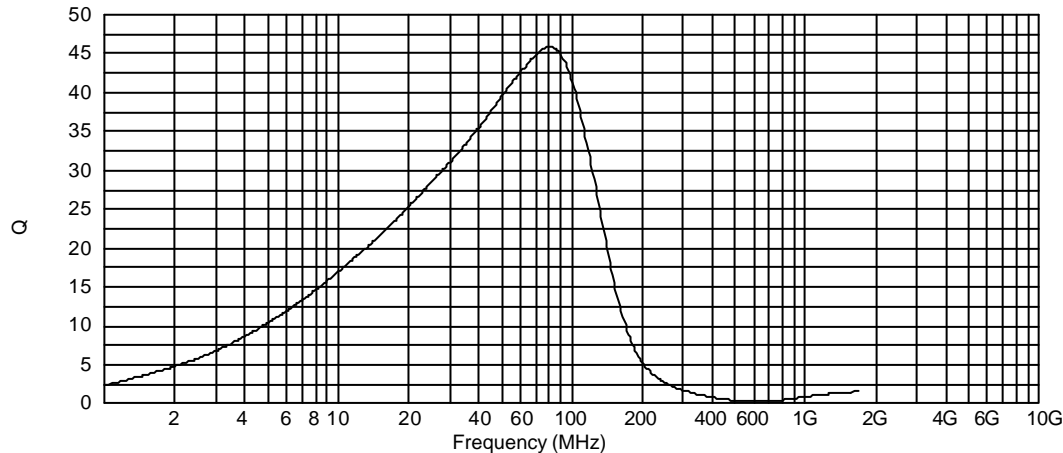
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.068	10	0.25	250	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

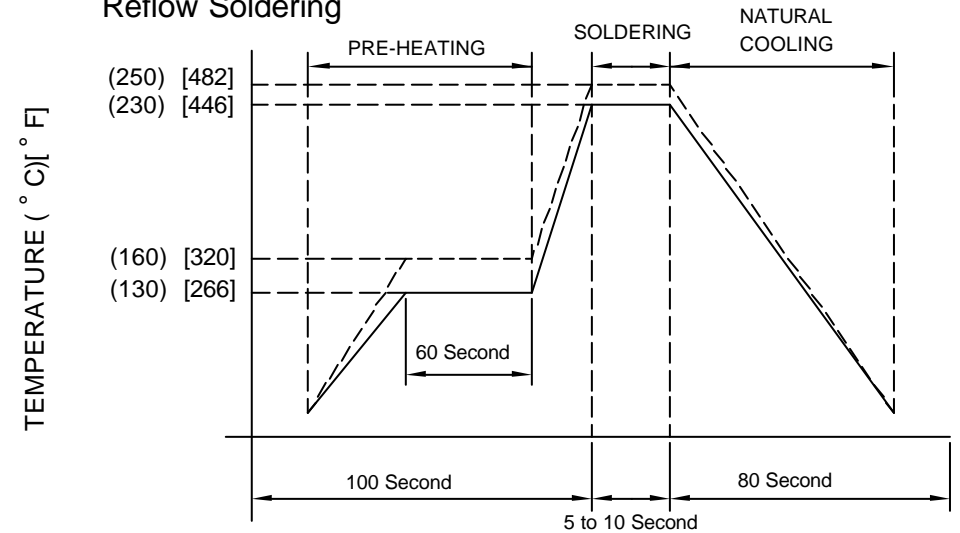
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

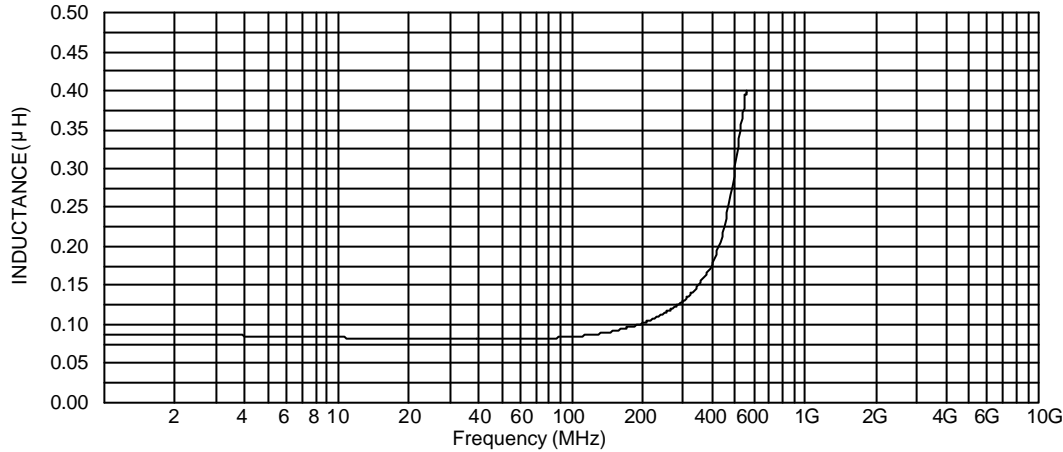
For lead free solder - - - - -

BCCL-1608E1-R082M

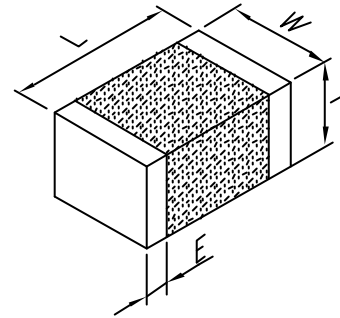
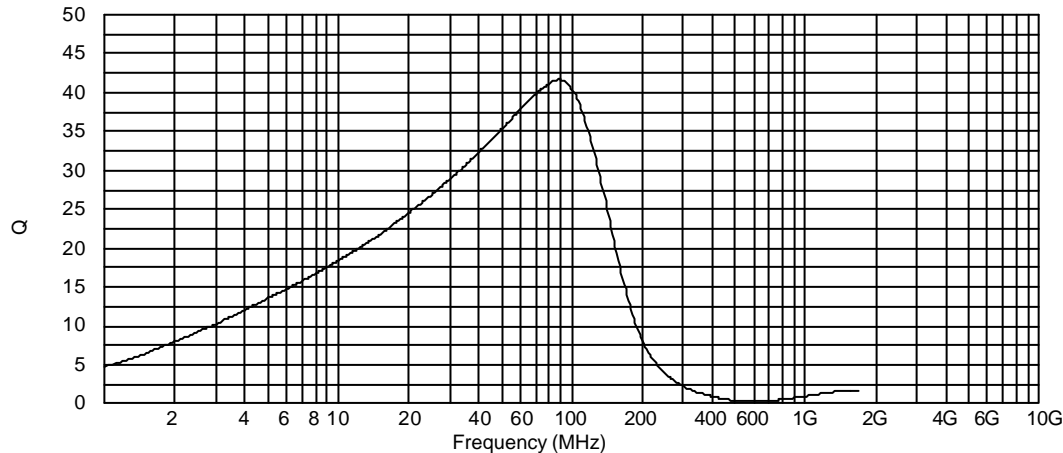
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.082	10	0.25	245	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

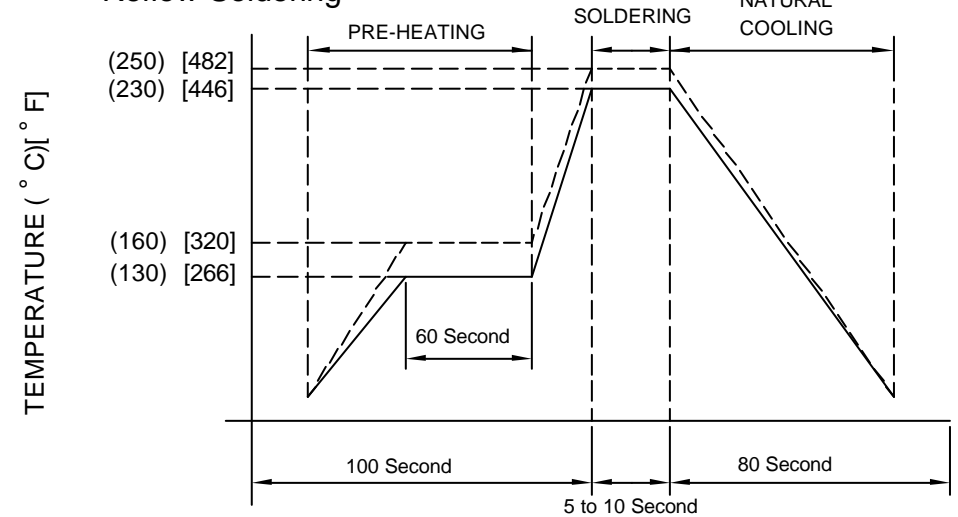
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

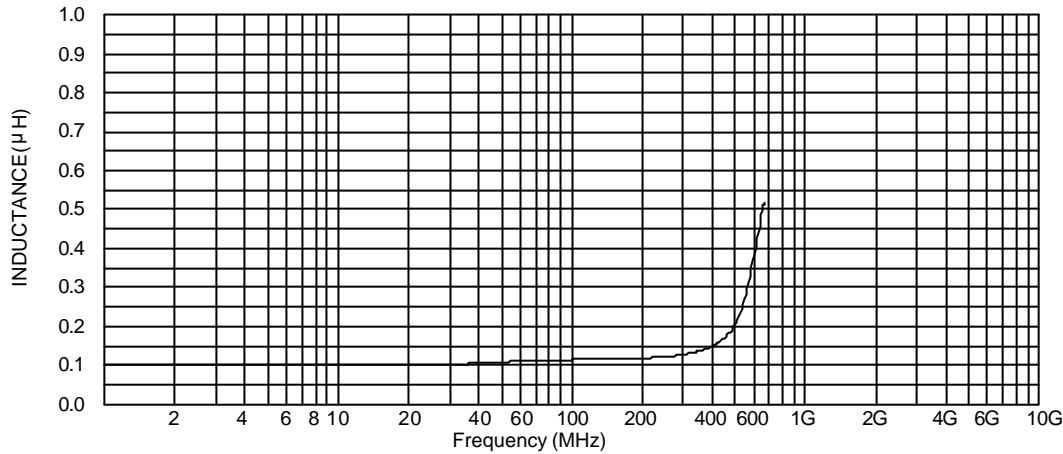
For lead free solder - - - - -

BCCL-1608E1-R10K

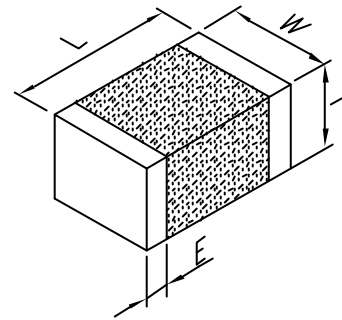
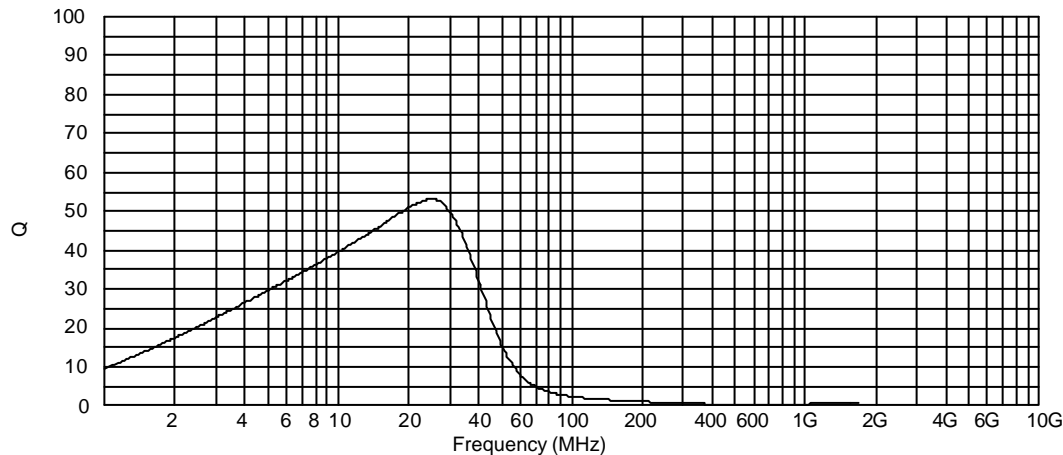
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.10	15	0.50	240	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

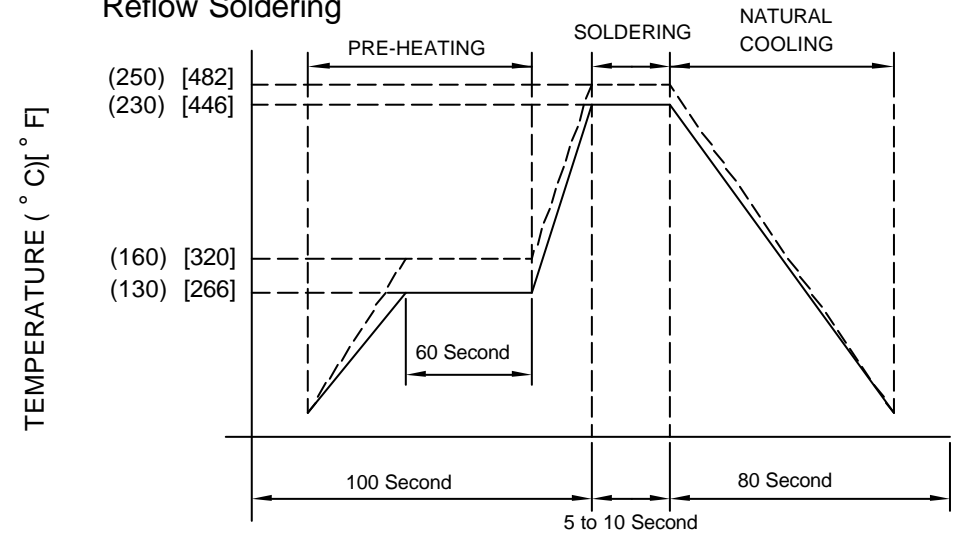
- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

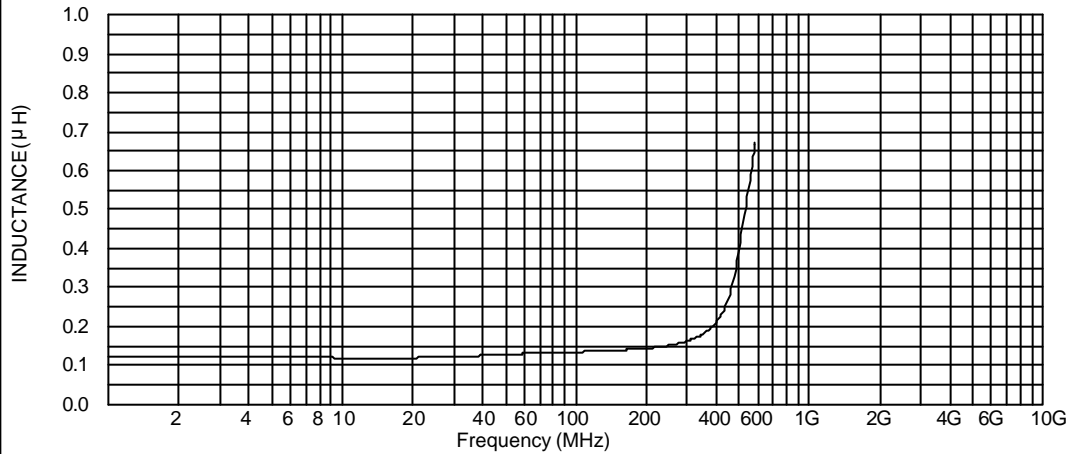
For lead free solder - - - - -

BCCL-1608E1-R12K

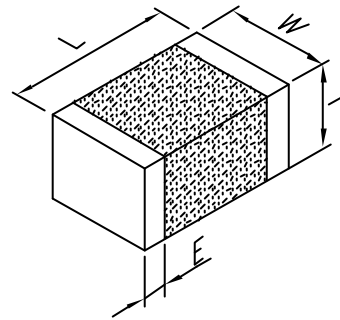
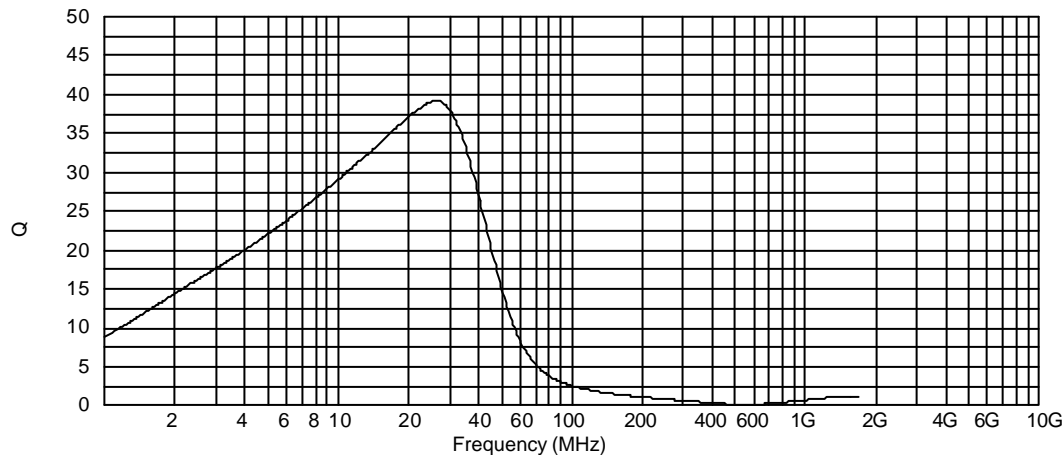
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.12	15	0.5	235	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

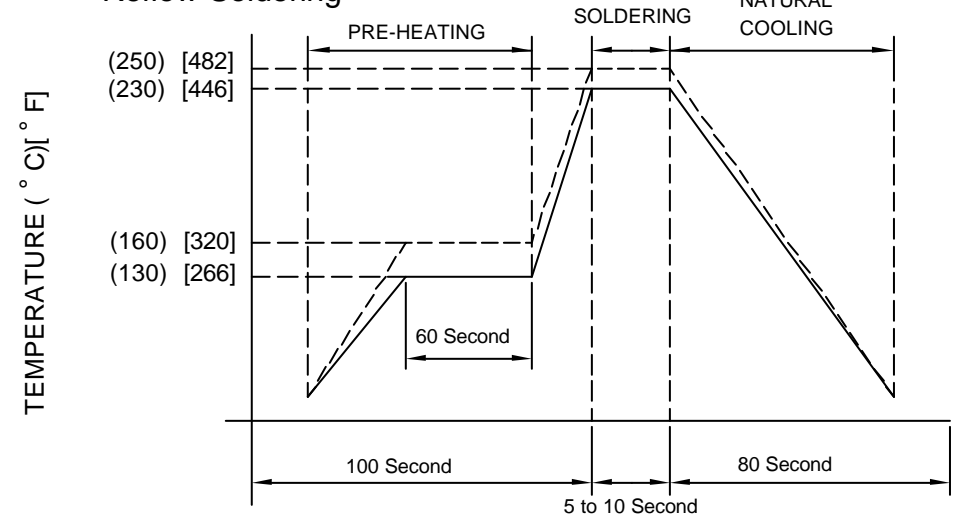
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



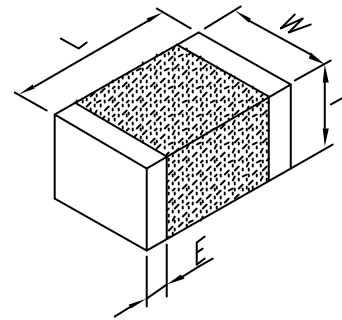
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-R15K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.15	15	0.60	205	50



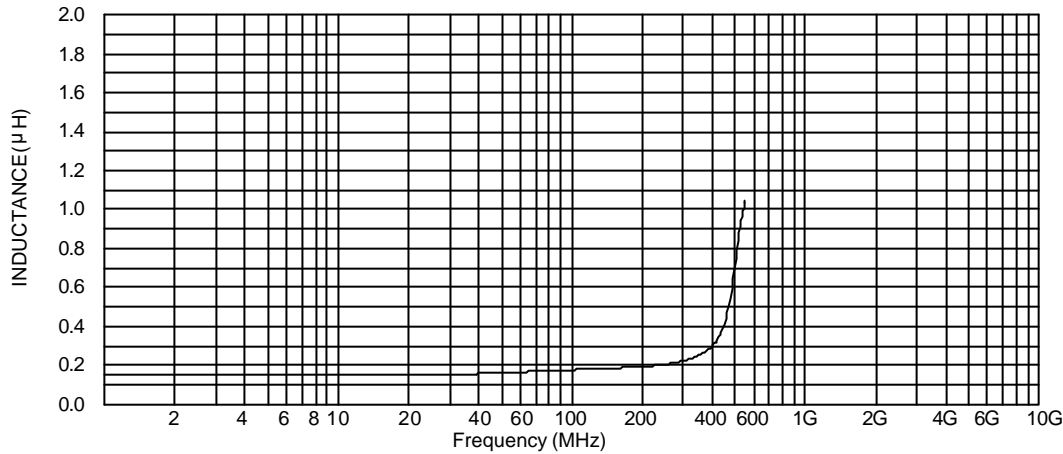
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

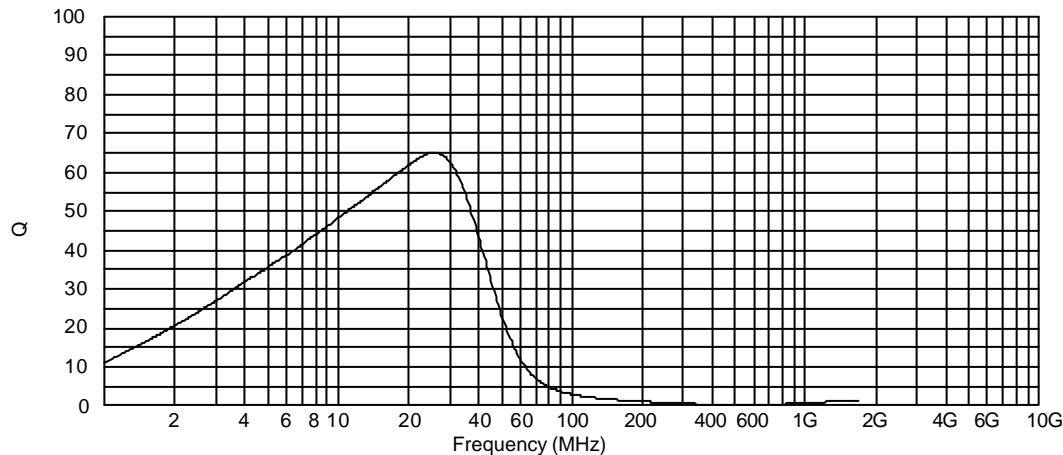
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

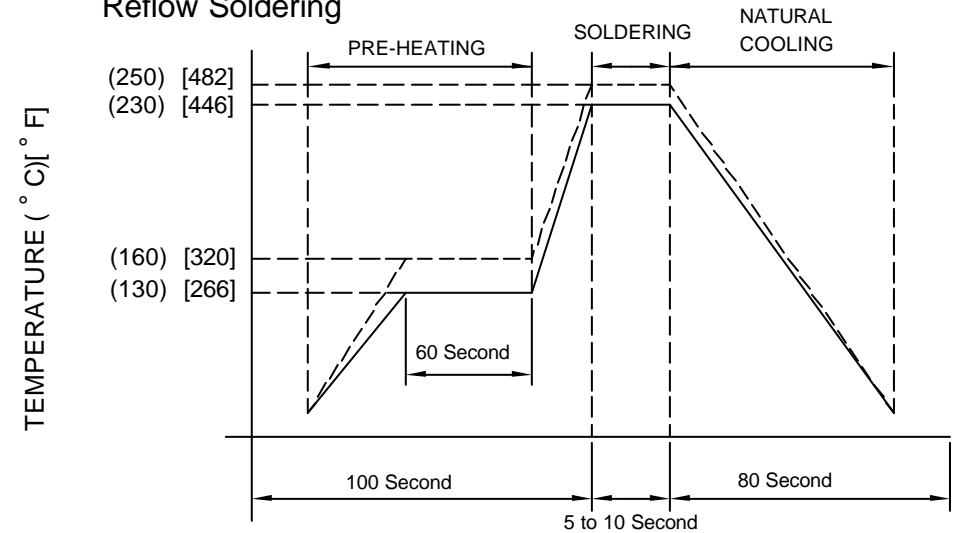


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

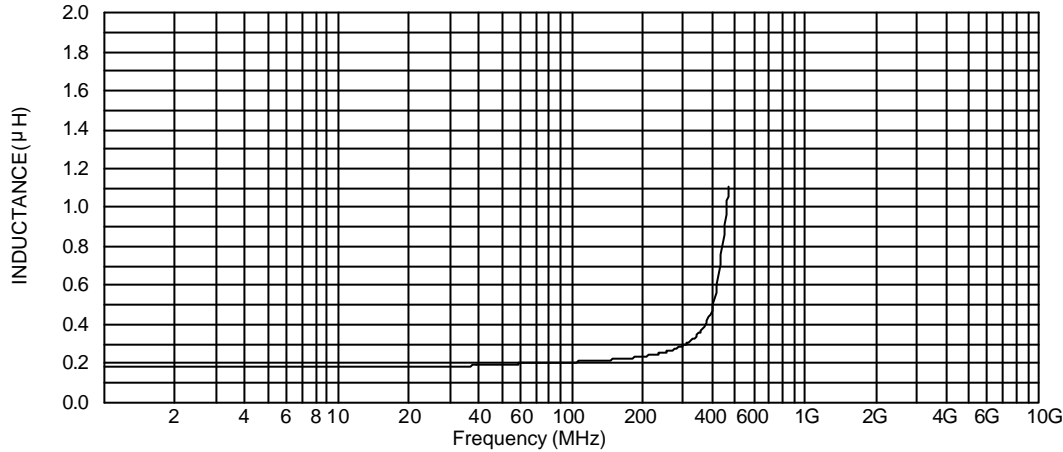
For lead free solder - - - - -

BCCL-1608E1-R18K

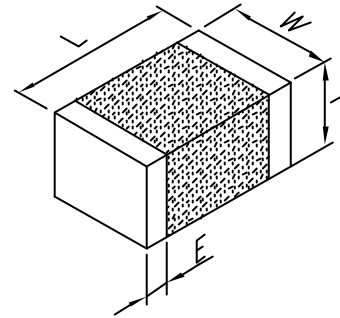
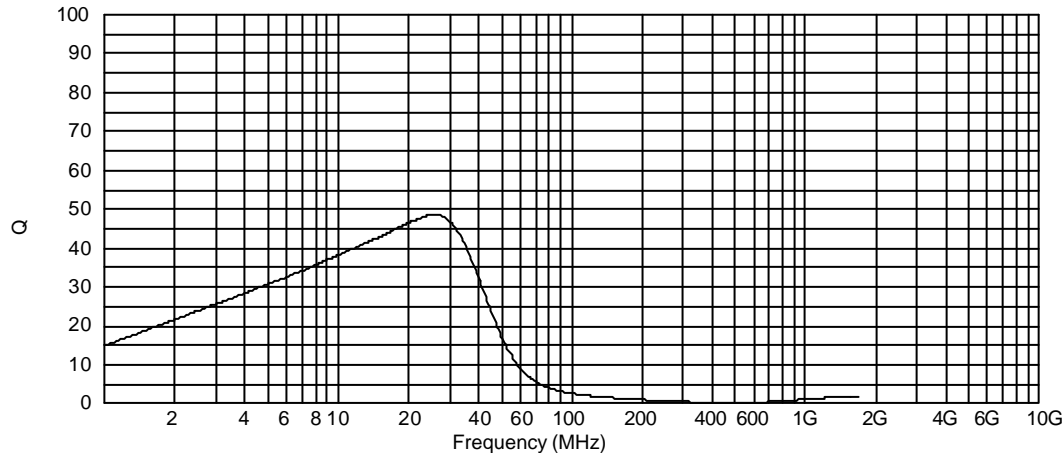
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.18	15	0.60	190	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

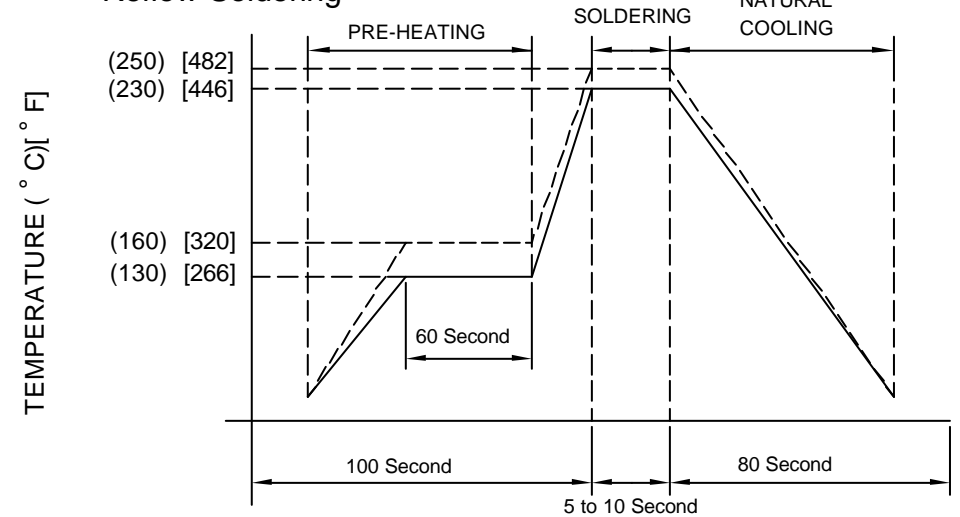
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



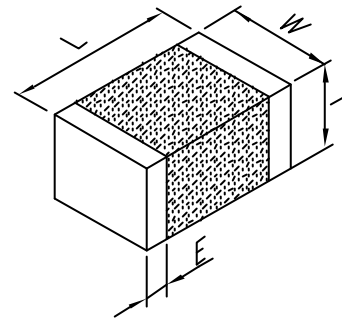
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-R22K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.22	15	0.80	170	50



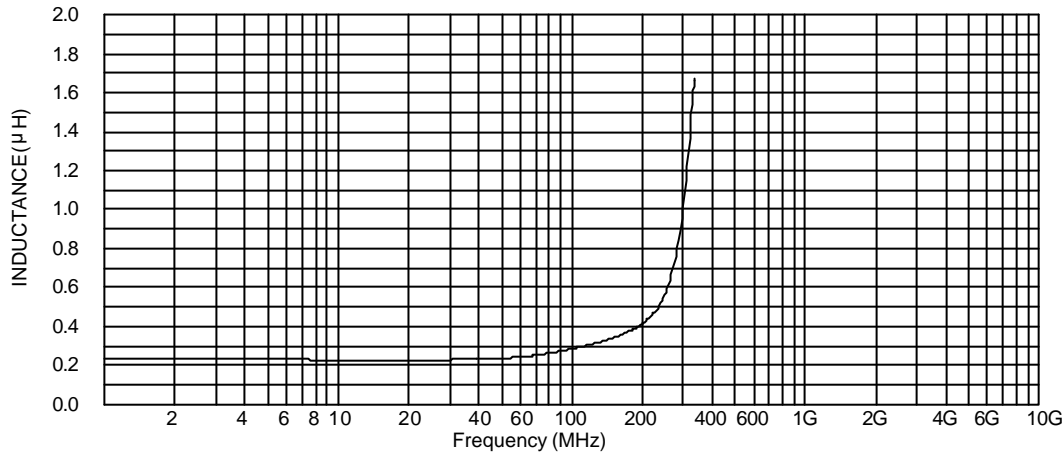
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

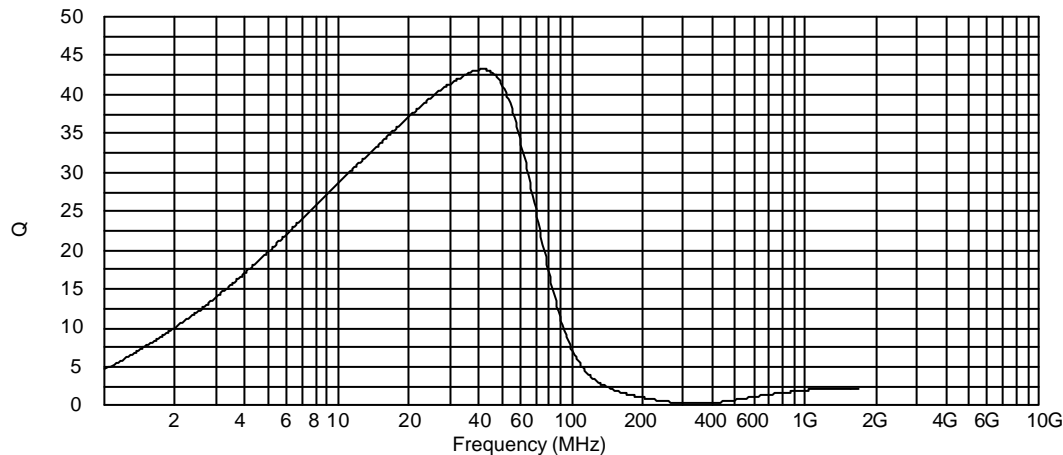
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

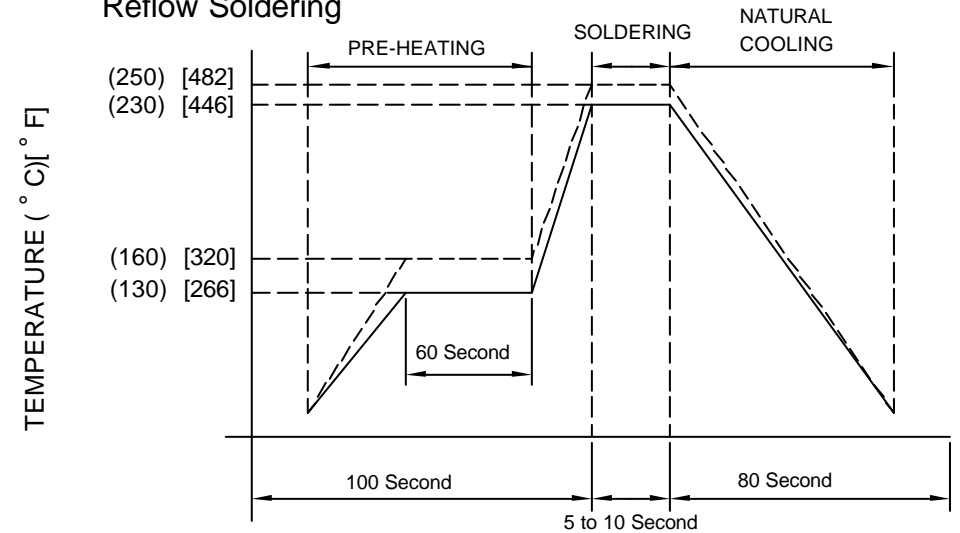


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

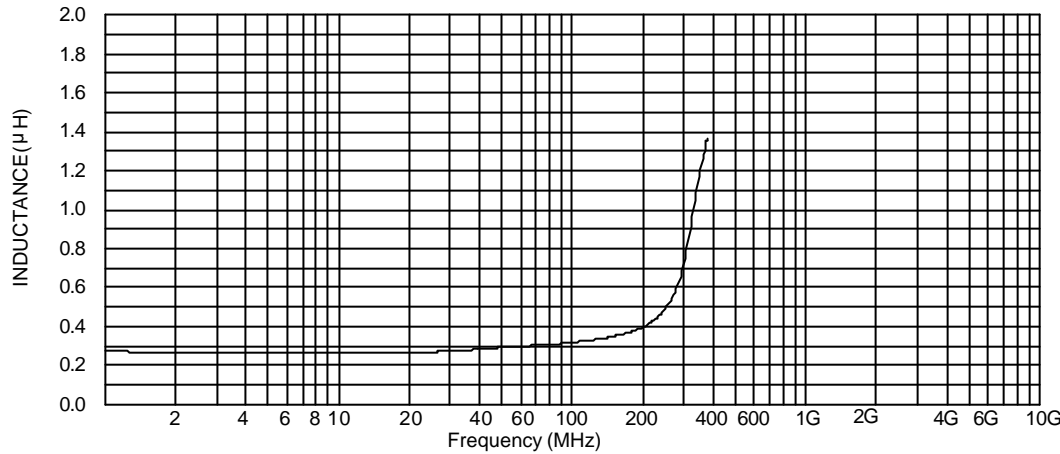
For lead free solder - - - - -

BCCL-1608E1-R27K

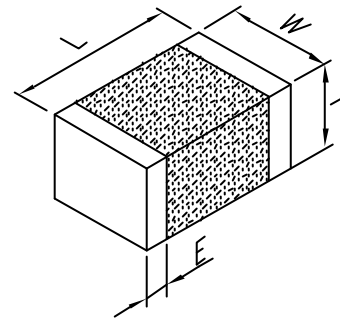
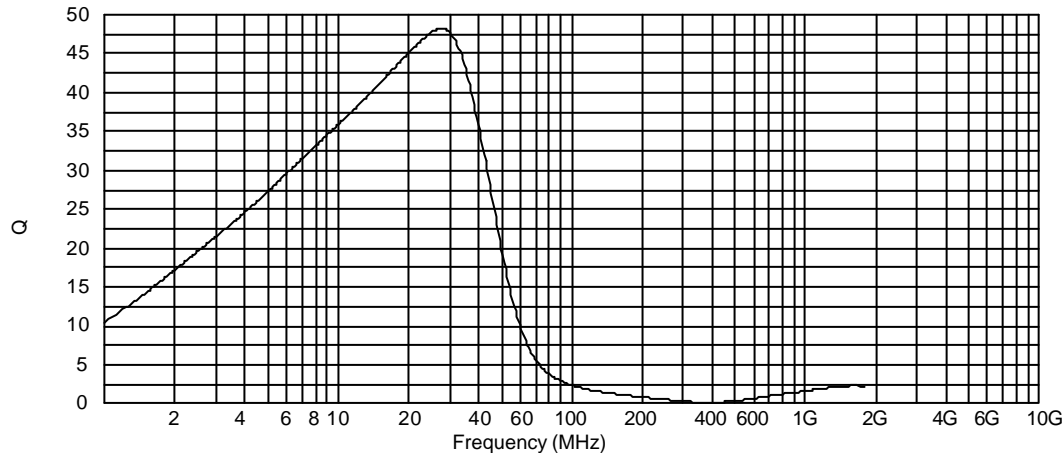
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.27	15	0.8	155	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

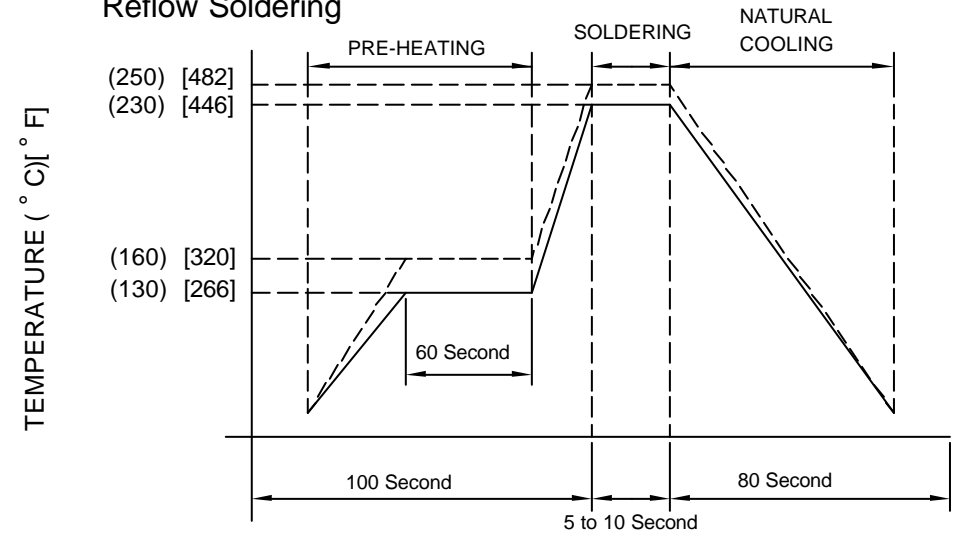
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



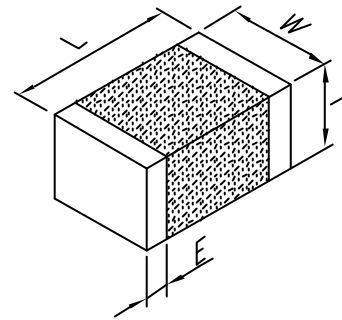
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-R33K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.33	15	0.8	140	35



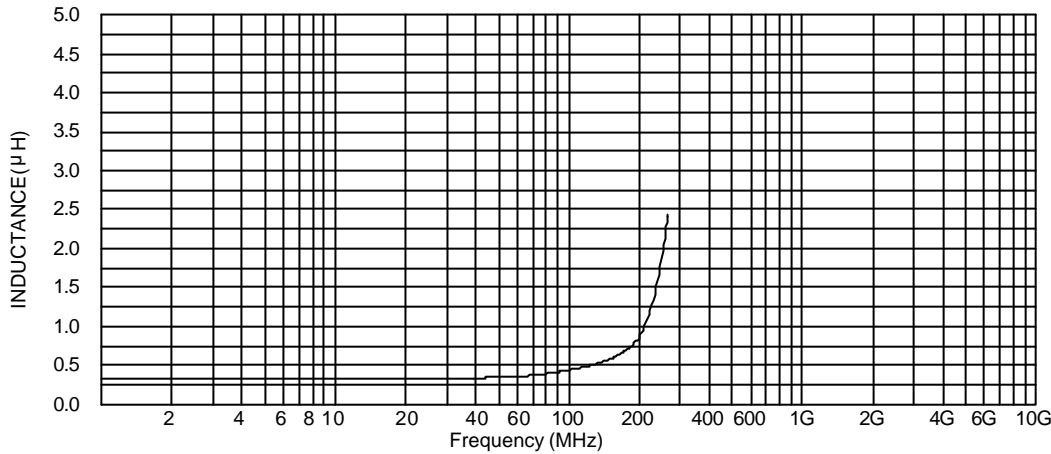
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

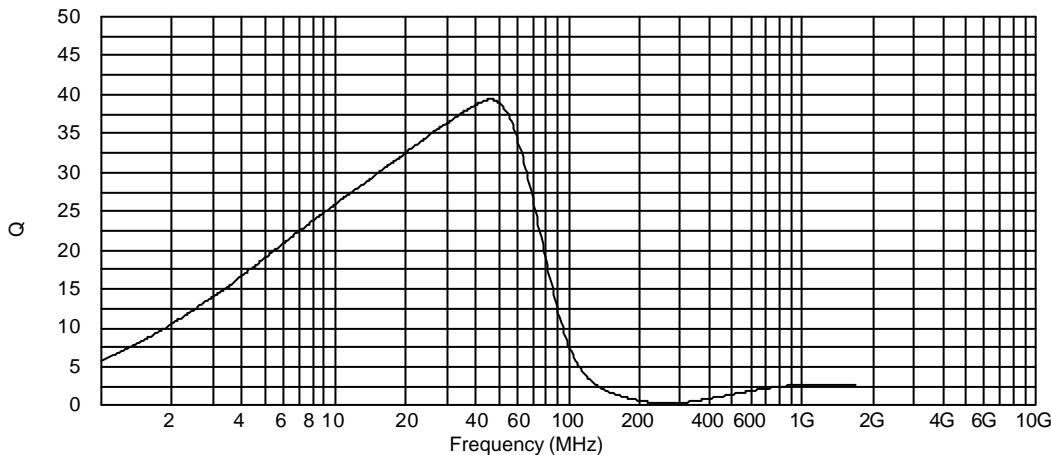
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

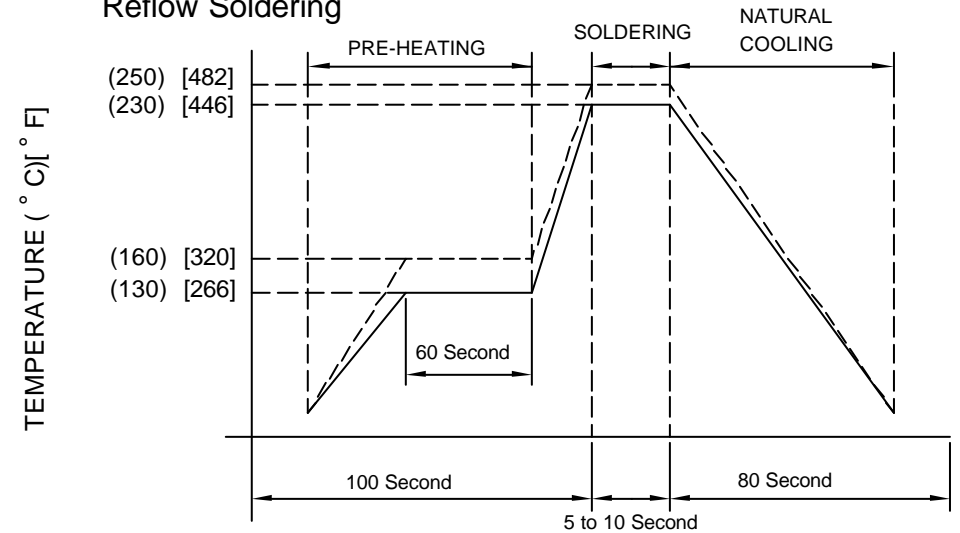


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



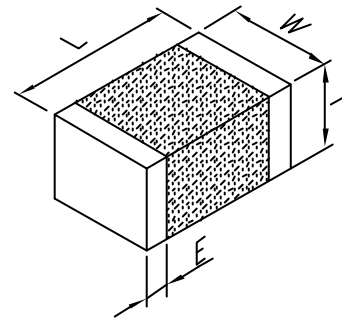
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-R39K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.39	15	1.0	125	35



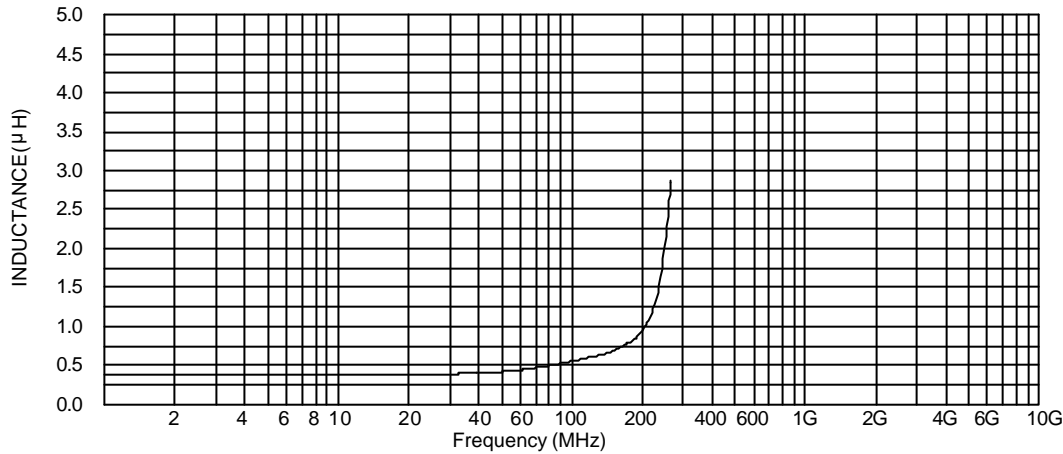
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

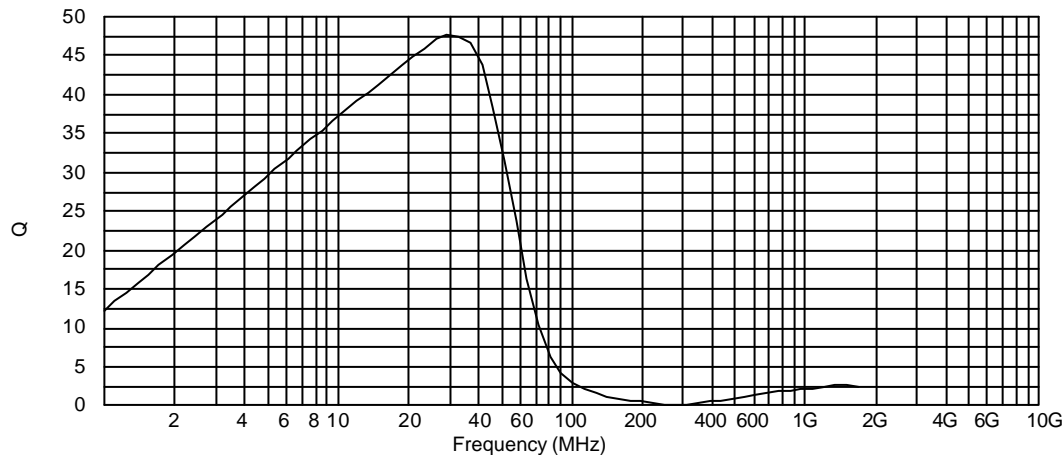
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

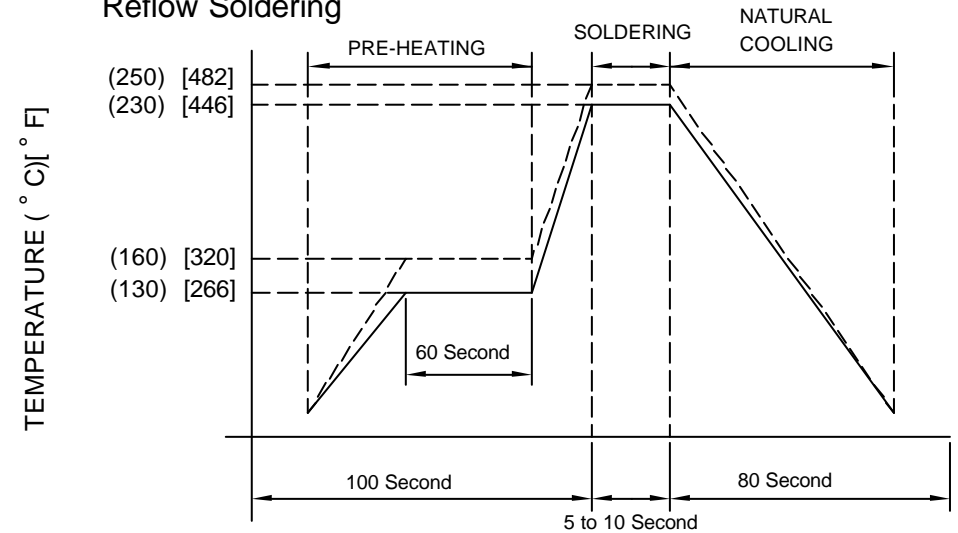


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



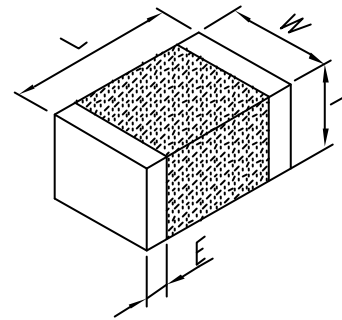
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-R47K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.47	15	1.0	120	35



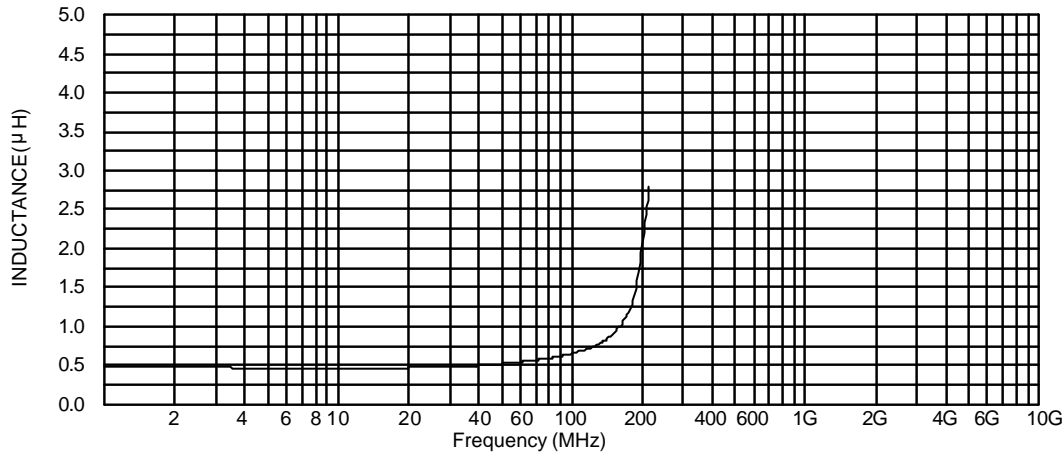
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

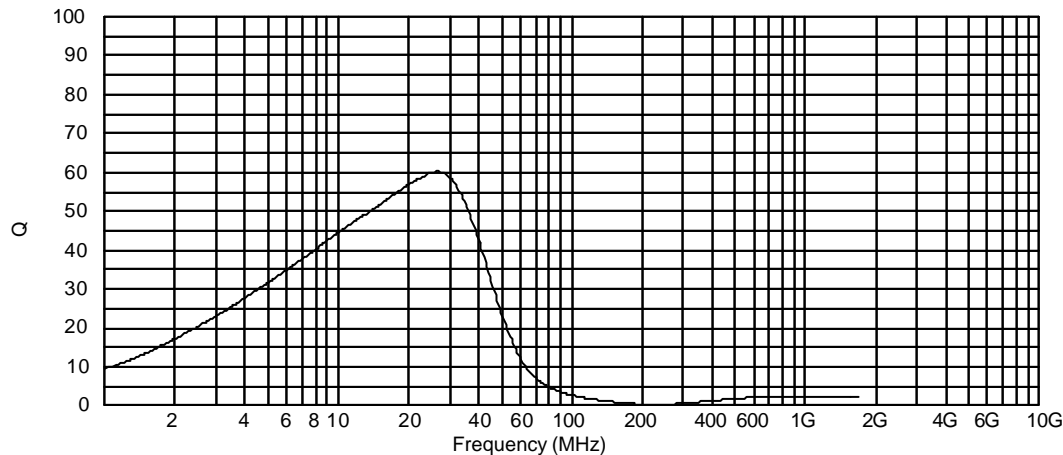
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

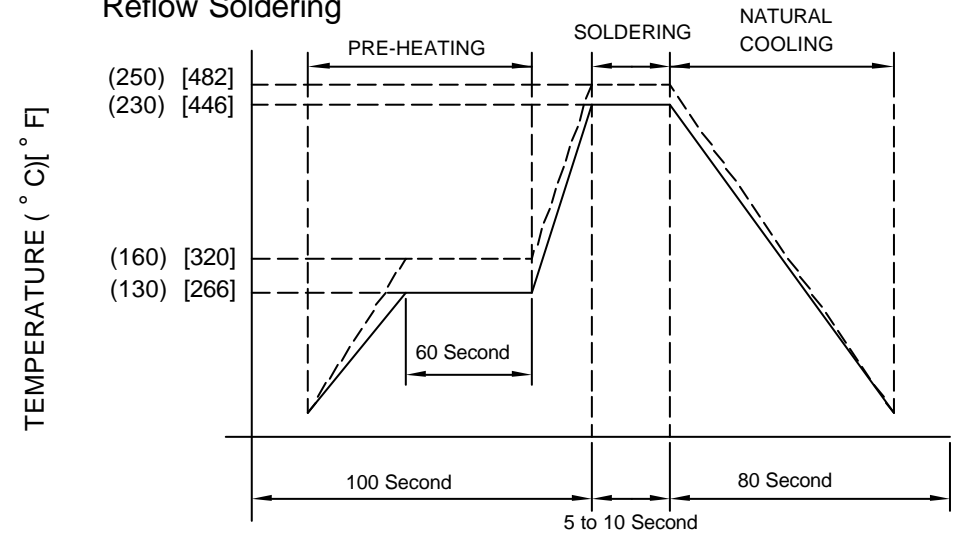


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

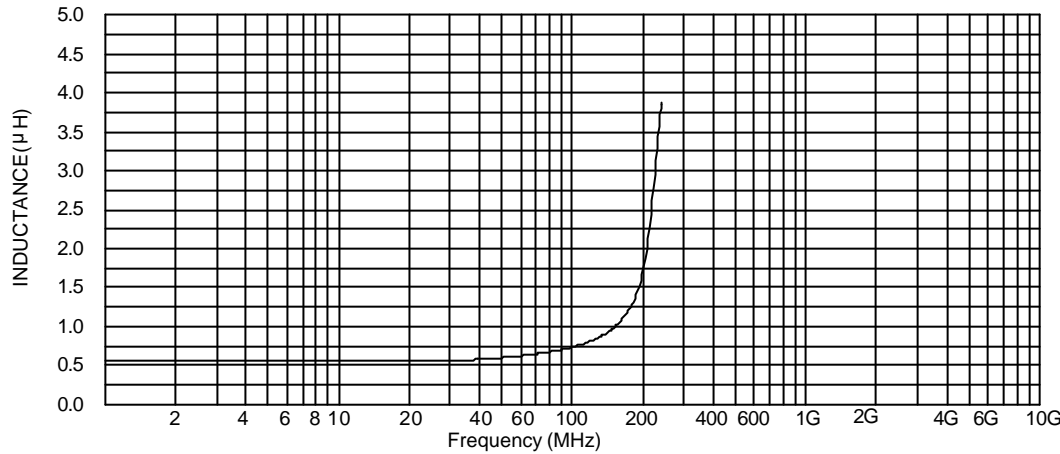
For lead free solder - - - - -

BCCL-1608E1-R56K

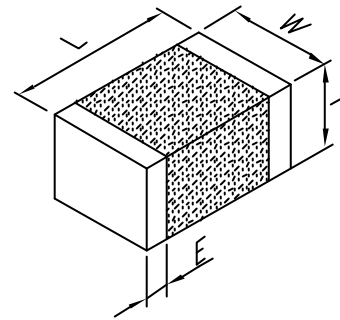
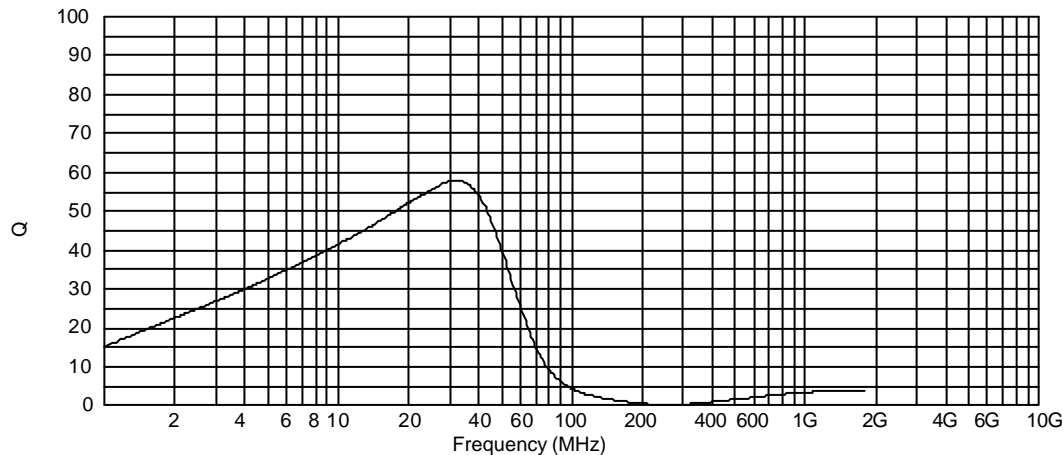
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.56	15	1.55	110	35

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

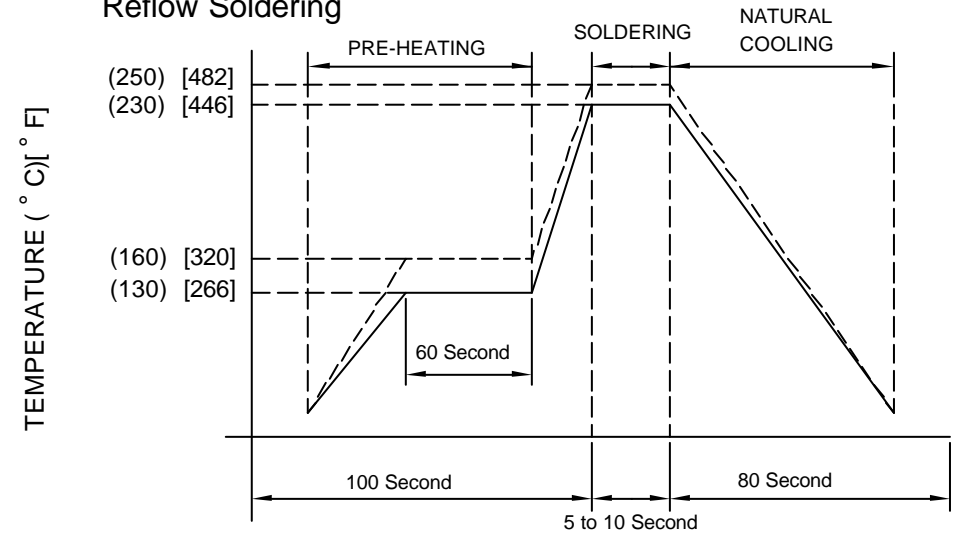
- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

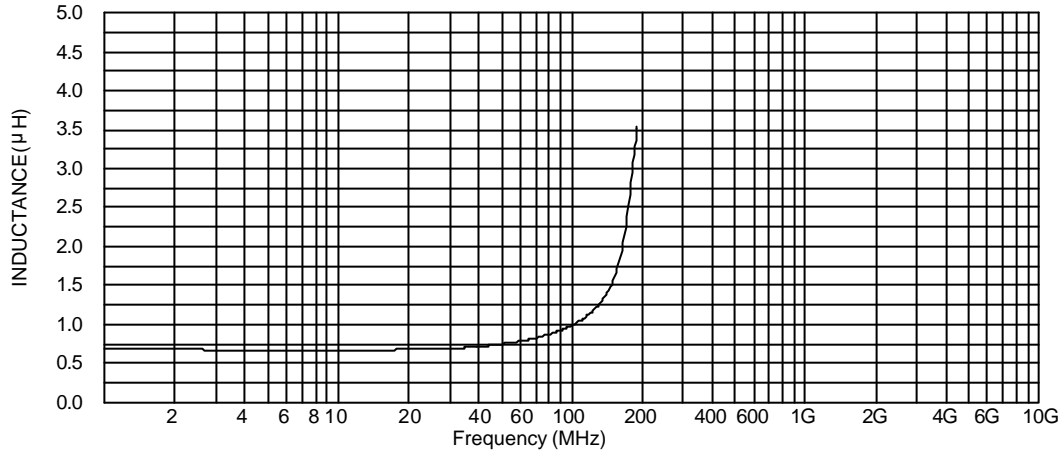
For lead free solder - - - - -

BCCL-1608E1-R68K

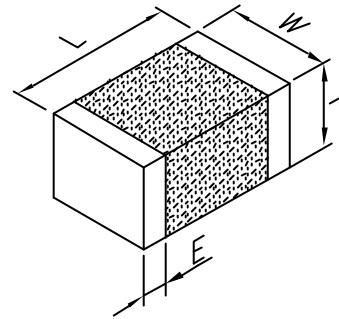
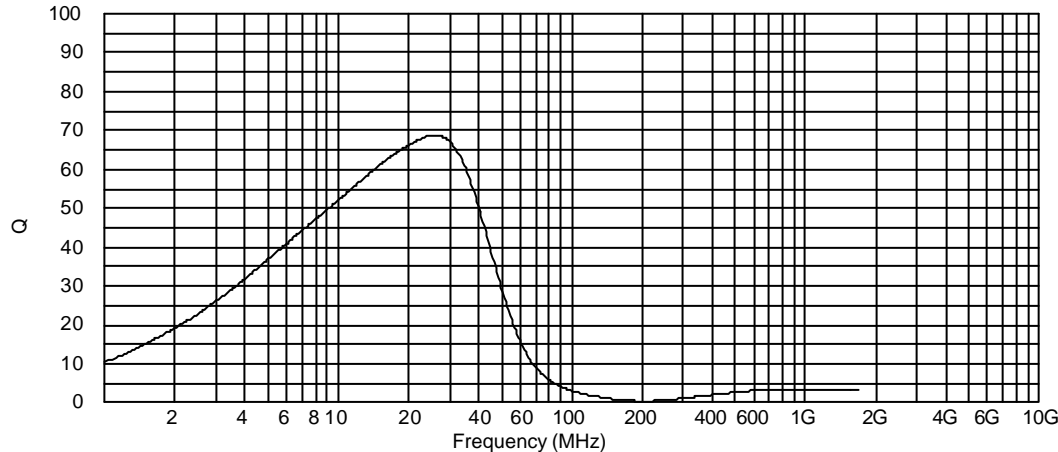
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.68	15	1.70	100	35

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

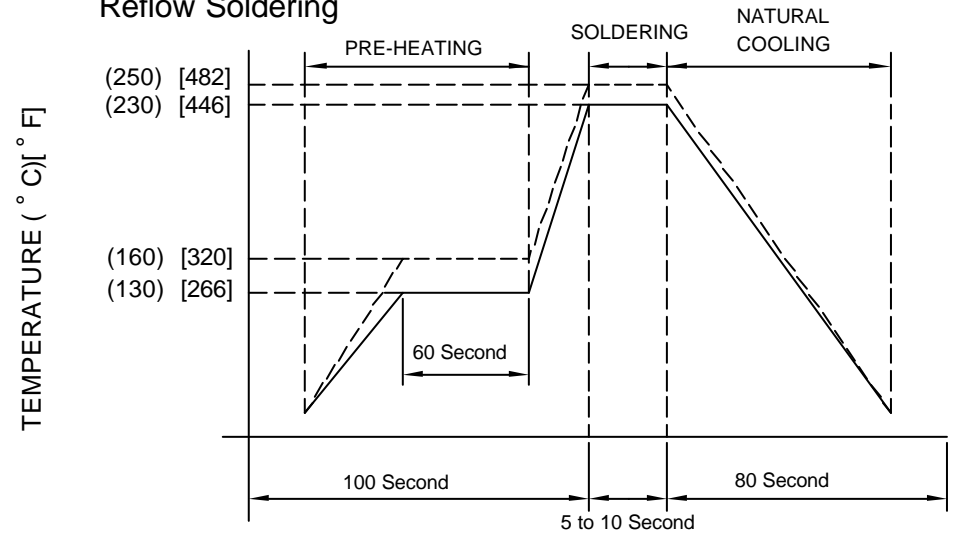
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

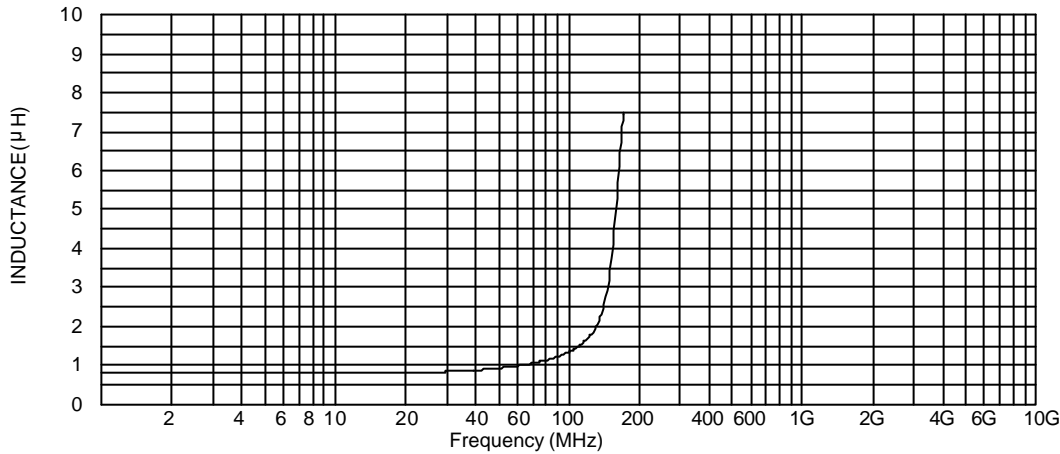
For lead free solder - - - - -

BCCL-1608E1-R82K

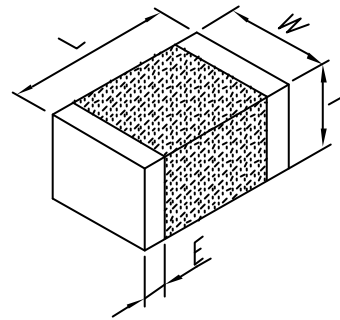
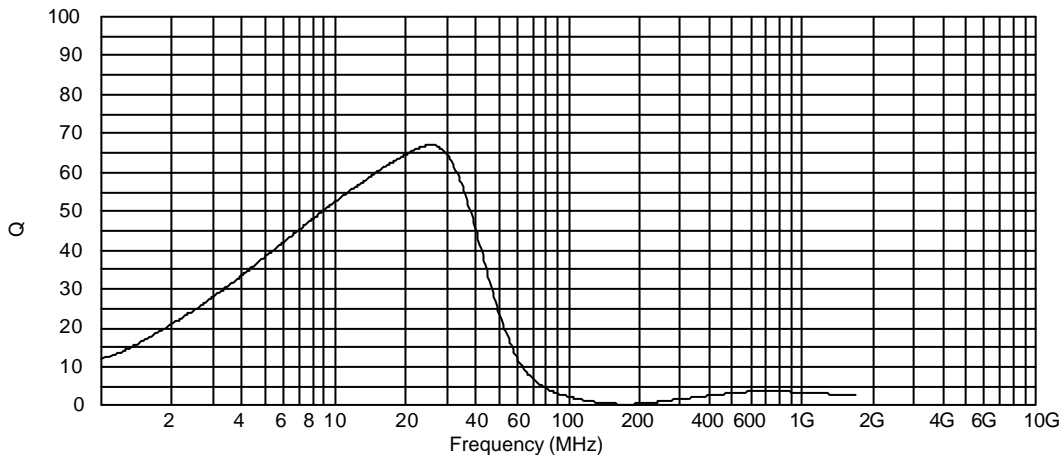
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.82	15	2.1	95	35

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

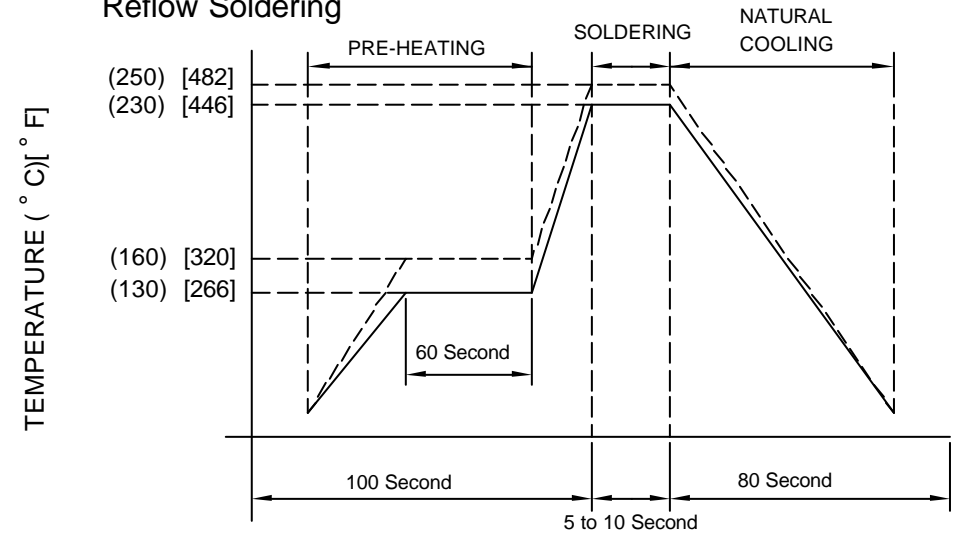
- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

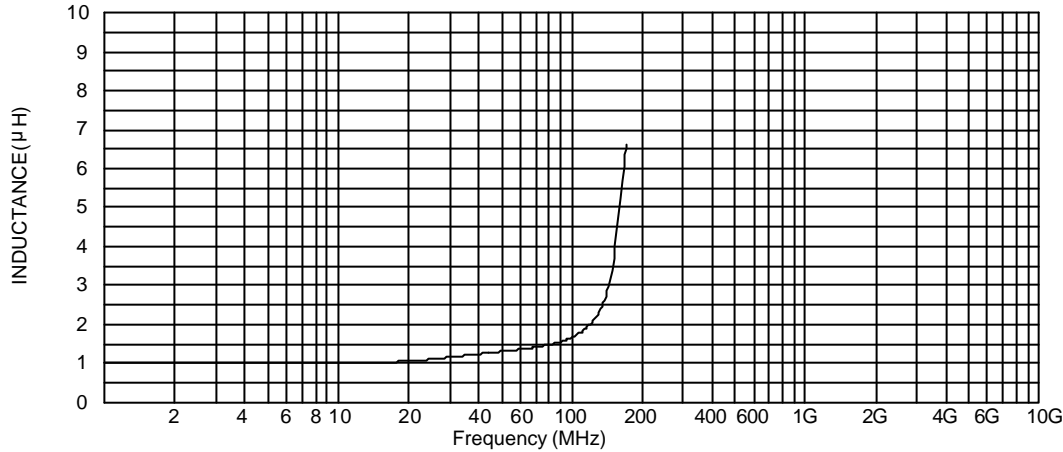
For lead free solder - - - - -

BCCL-1608E1-1R0K

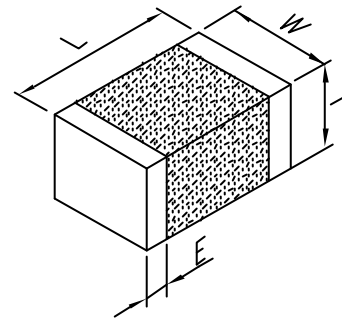
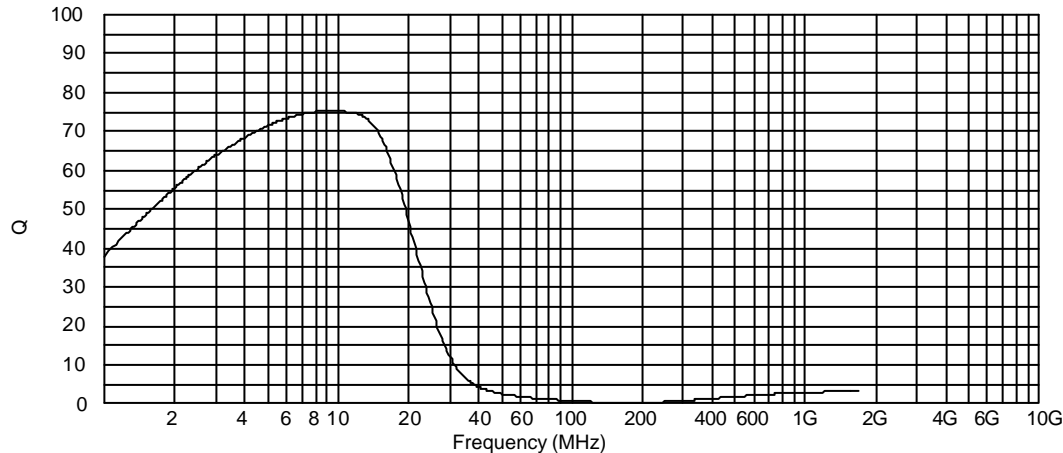
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.0	35	0.6	85	25

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

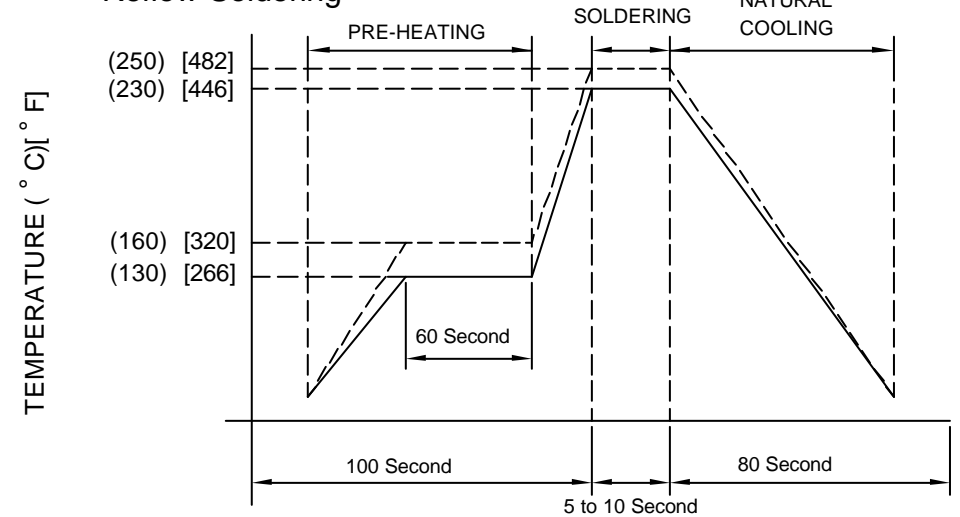
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

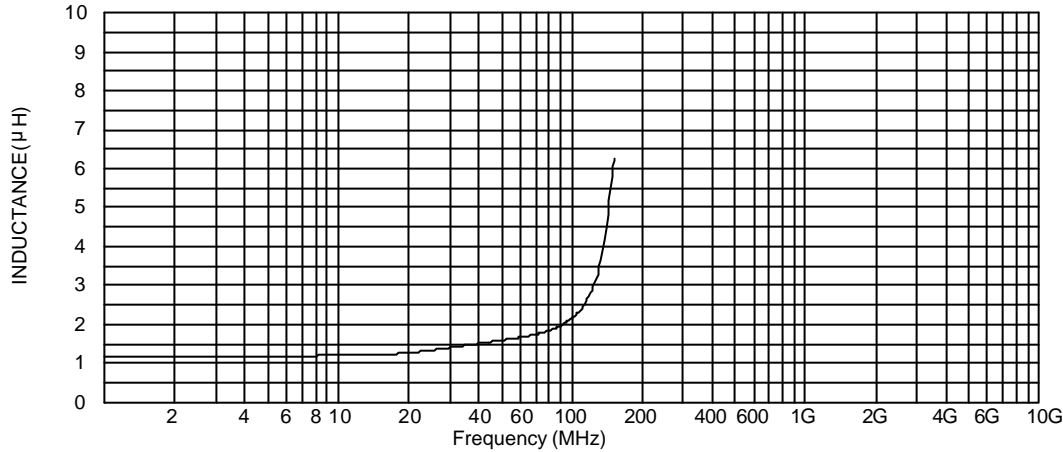
For lead free solder - - - - -

BCCL-1608E1-1R2K

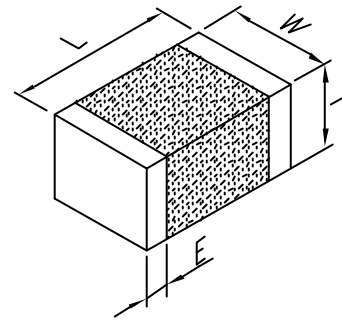
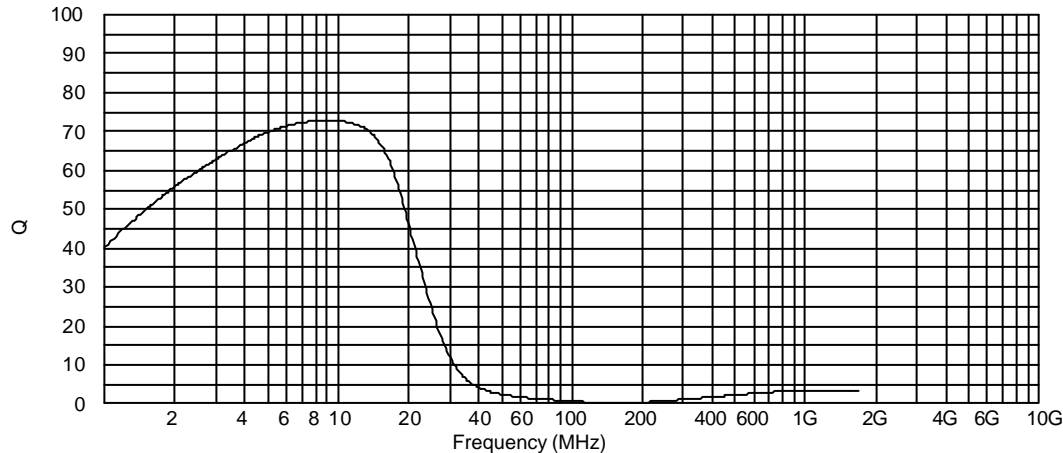
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.2	35	0.8	70	25

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

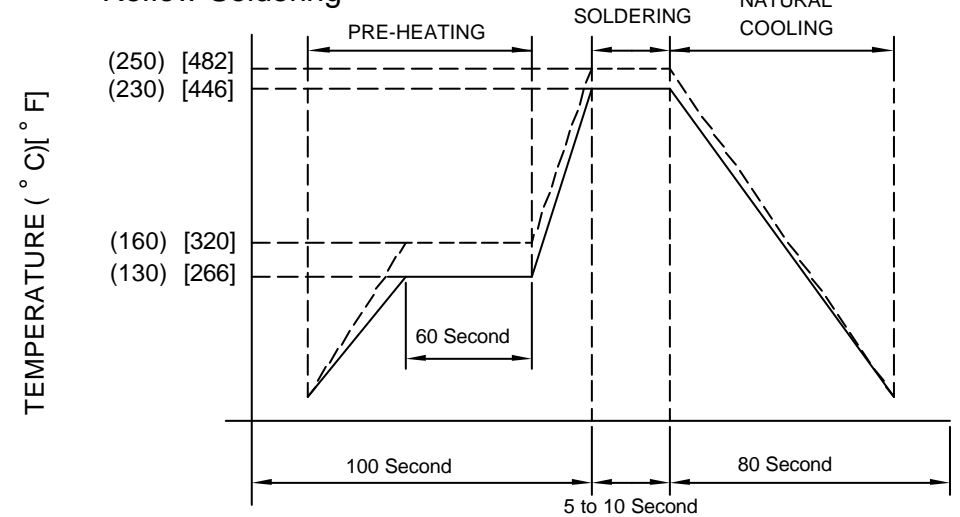
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



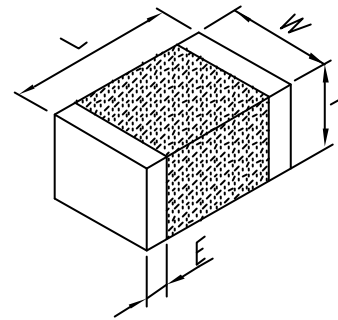
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-1R5K

ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.5	35	0.8	65	25



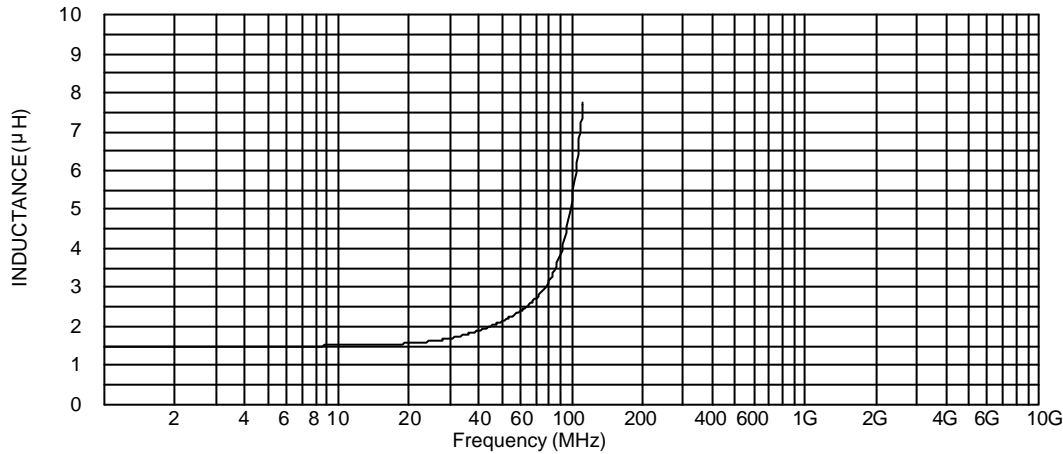
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

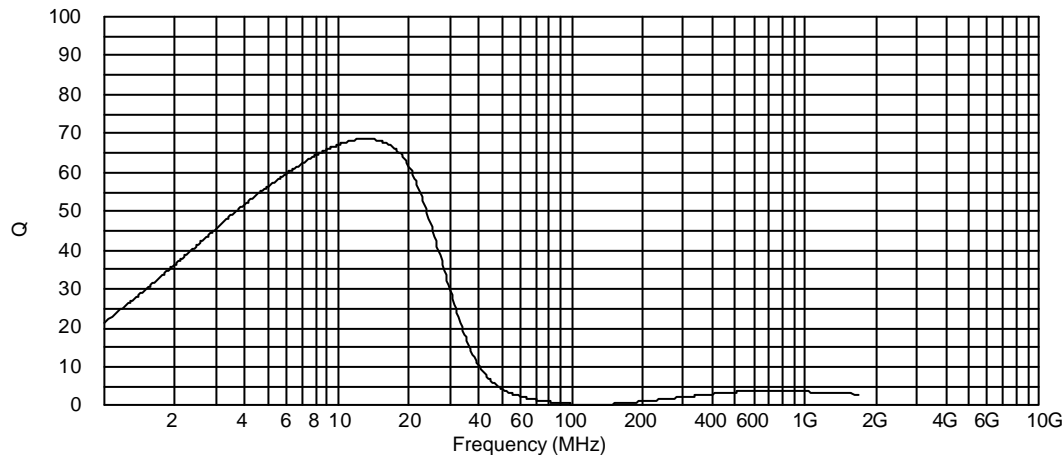
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

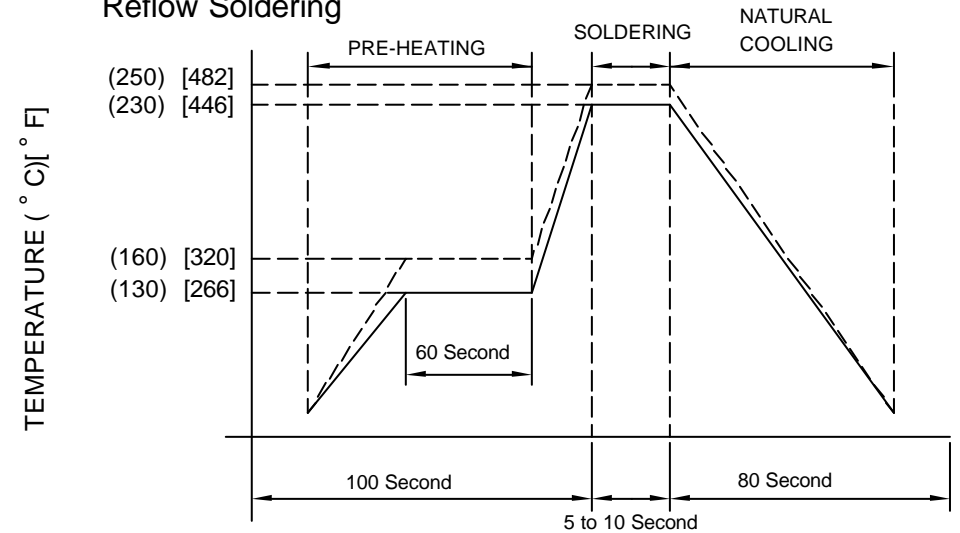


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

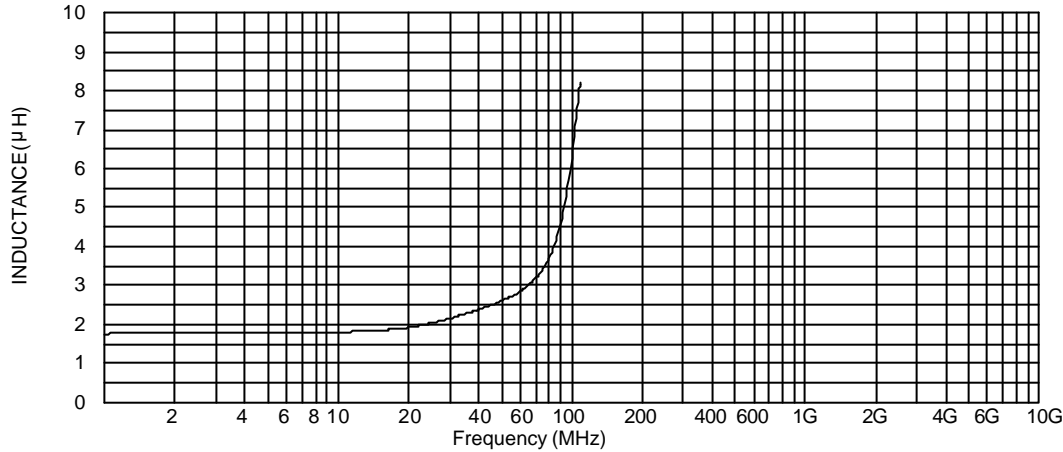
For lead free solder - - - - -

BCCL-1608E1-1R8K

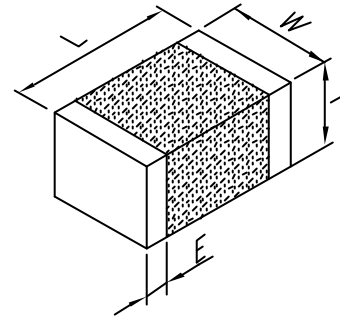
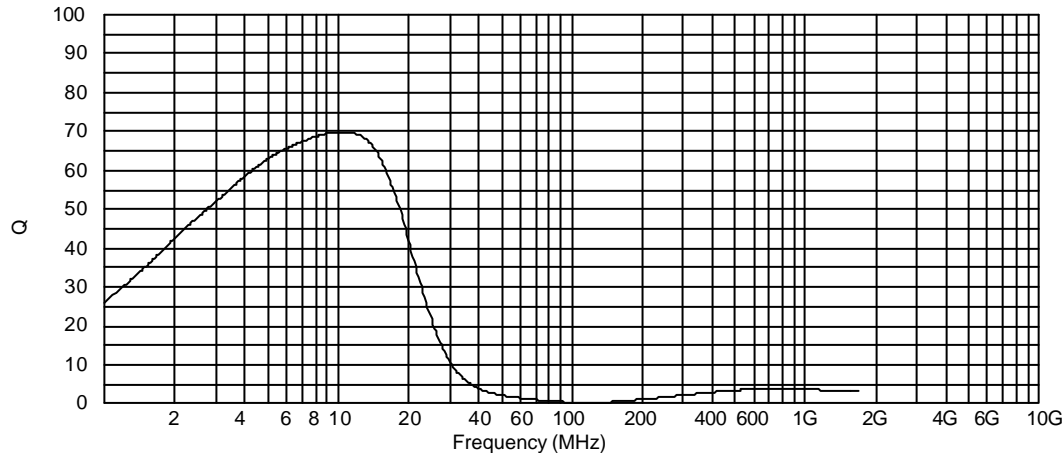
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.8	35	0.8	60	25

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

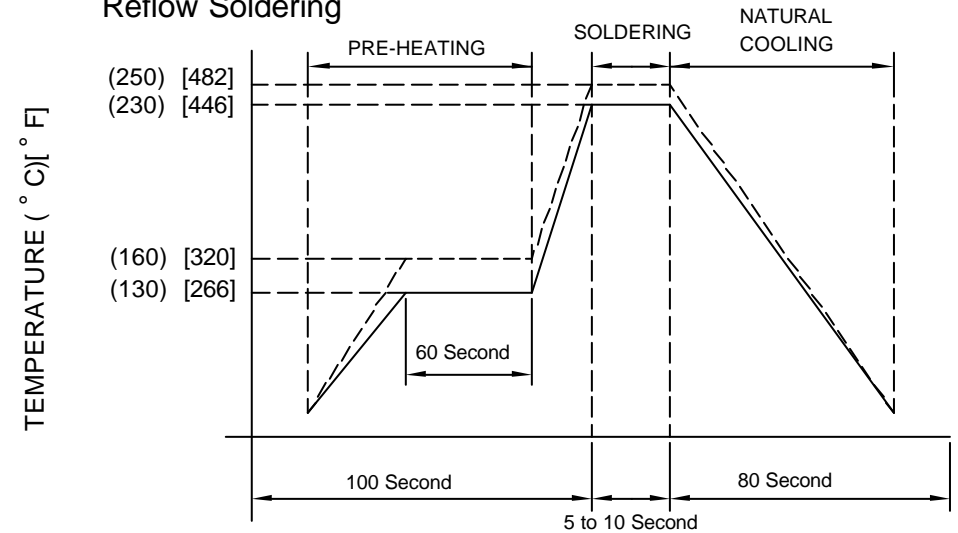
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering

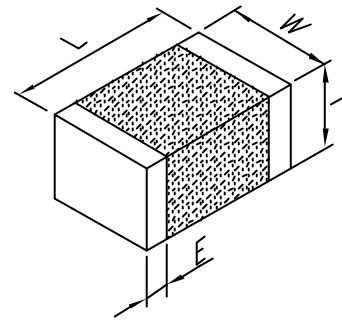


For Sn/Pb=63/37 solder _____
 For lead free solder - - - - -

BCCL-1608E1-2R2K

ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
2.2	35	1.0	55	15



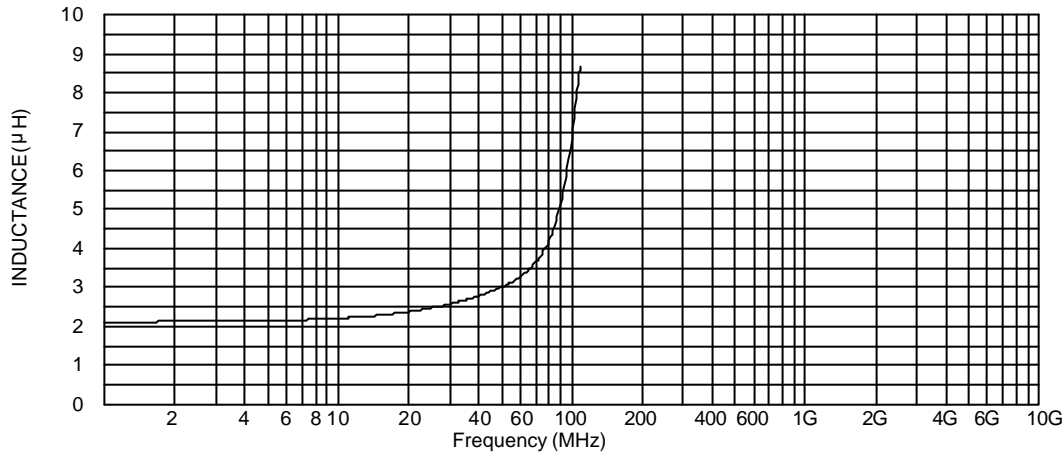
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

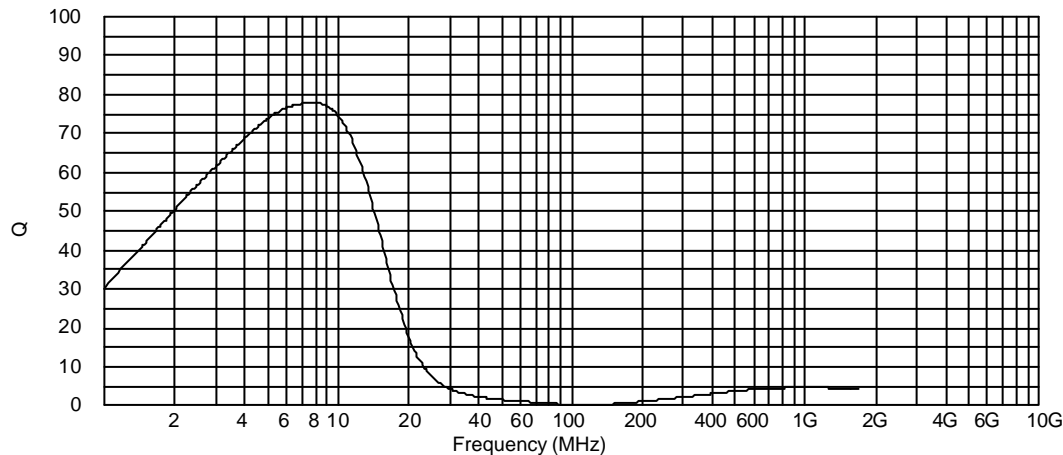
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

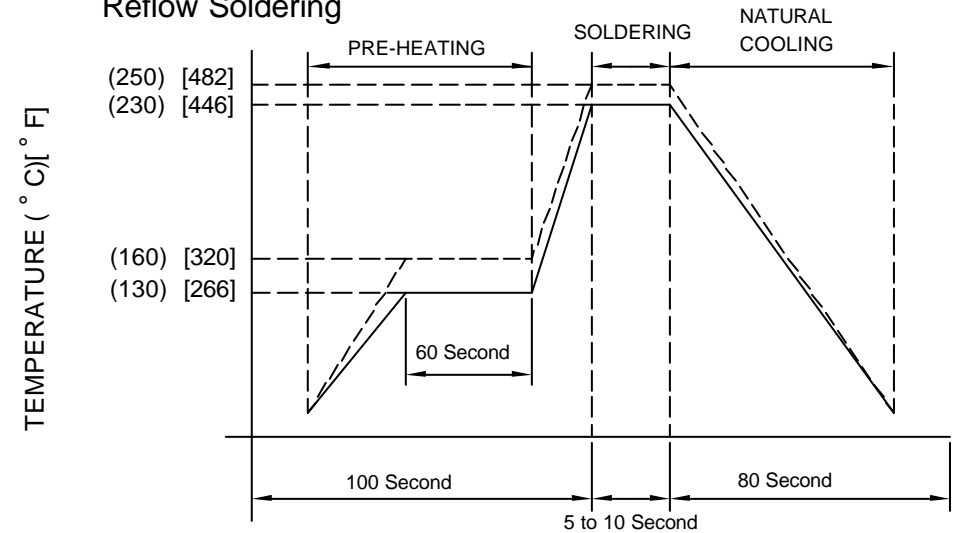


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

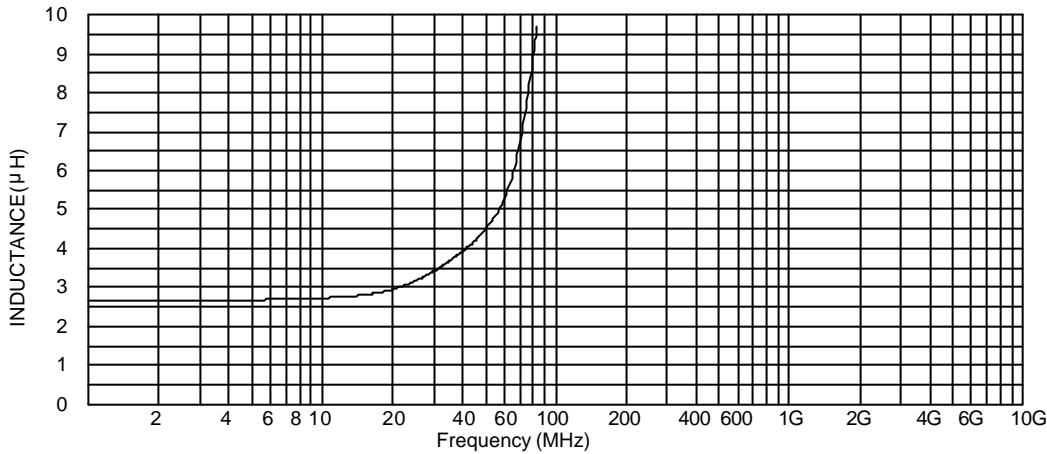
For lead free solder - - - - -

BCCL-1608E1- 2R7K

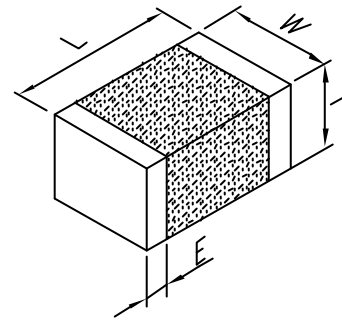
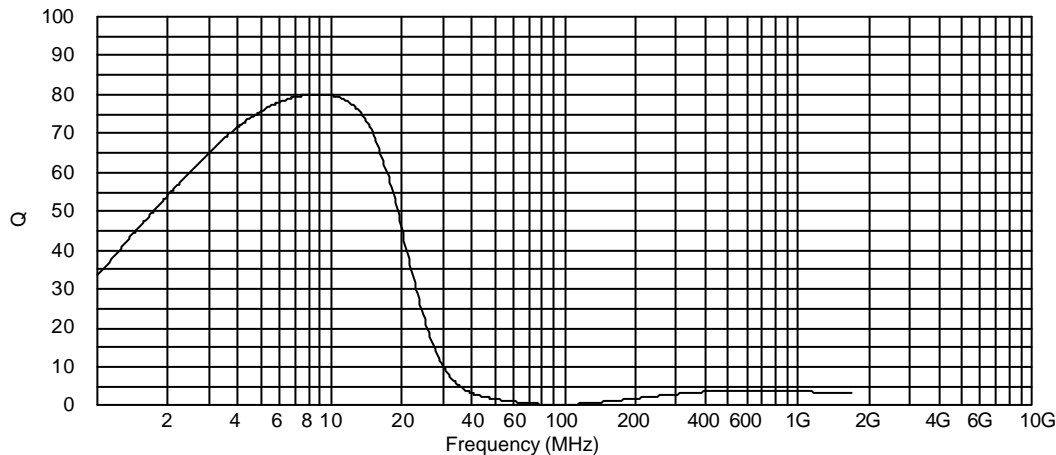
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
2.7	35	1.2	50	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

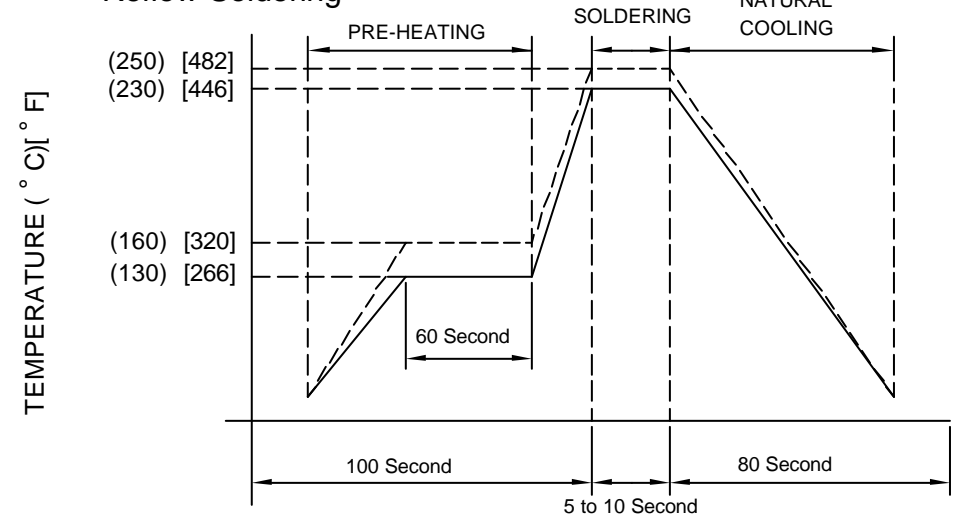
- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



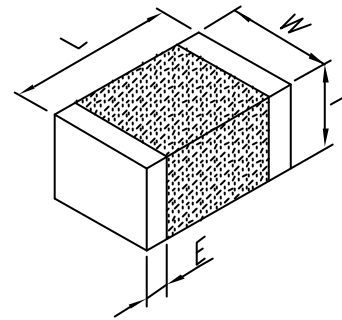
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-3R3K

ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
3.3	35	1.4	45	15



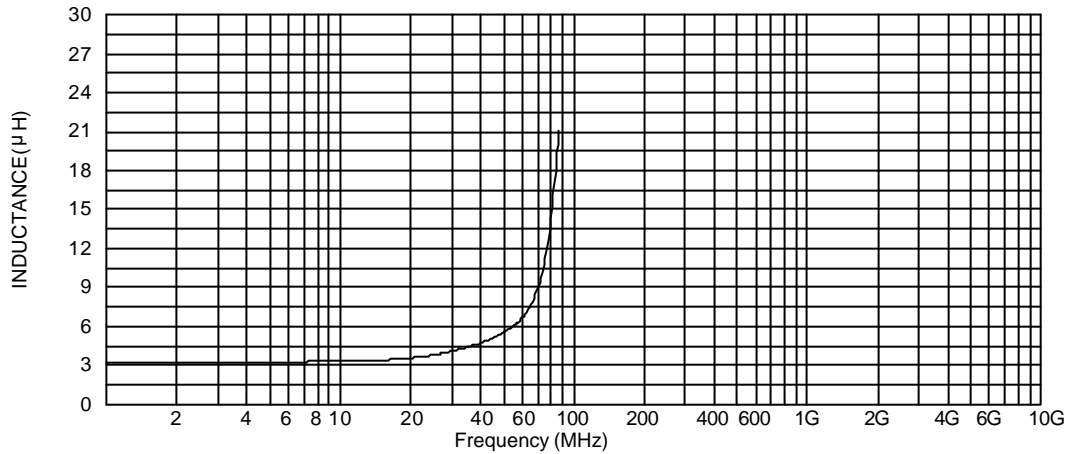
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

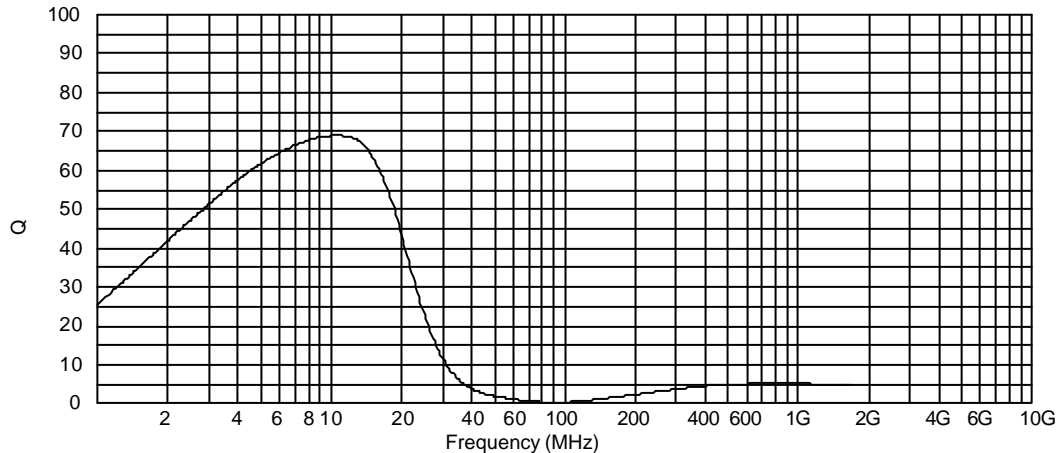
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

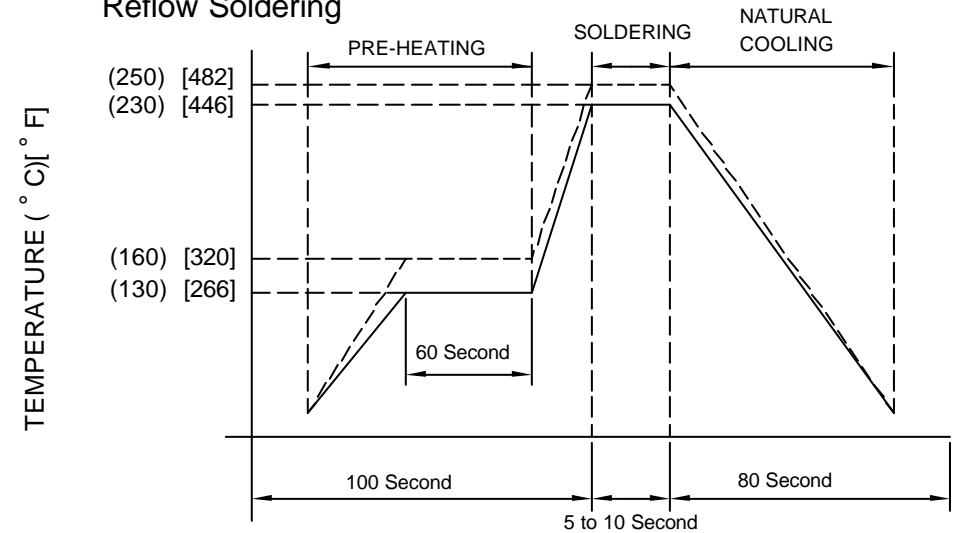


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



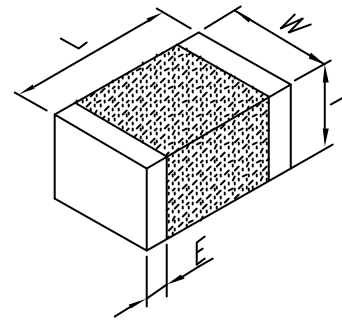
For Sn/Pb=63/37 solder _____

For lead free solder - - - - -

BCCL-1608E1-4R7K

ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu H \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
4.7	40	1.8	40	15



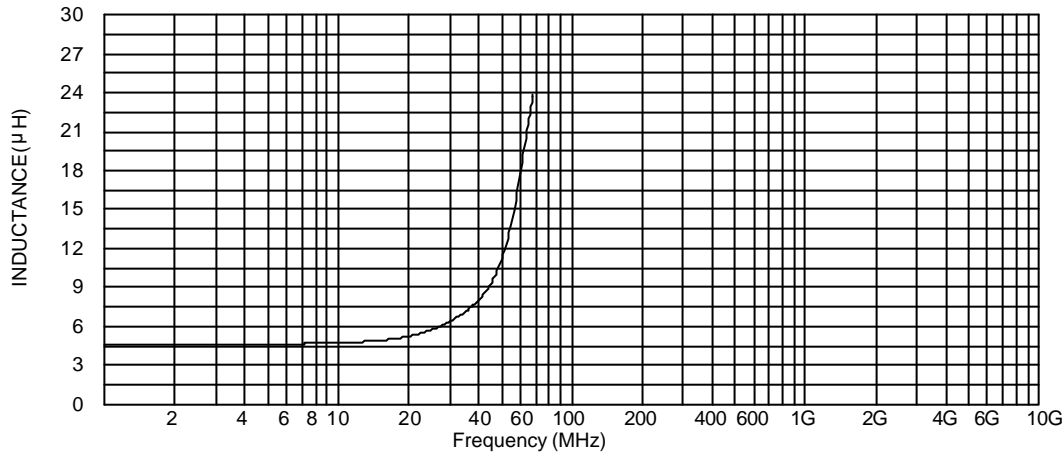
PHYSICAL DIMENSIONS:

- L 1.60(0.063) \pm 0.150(0.006)
- W 0.80(0.031) \pm 0.150(0.006)
- T 0.80(0.031) \pm 0.150(0.006)
- E 0.30(0.012) \pm 0.200(0.008)

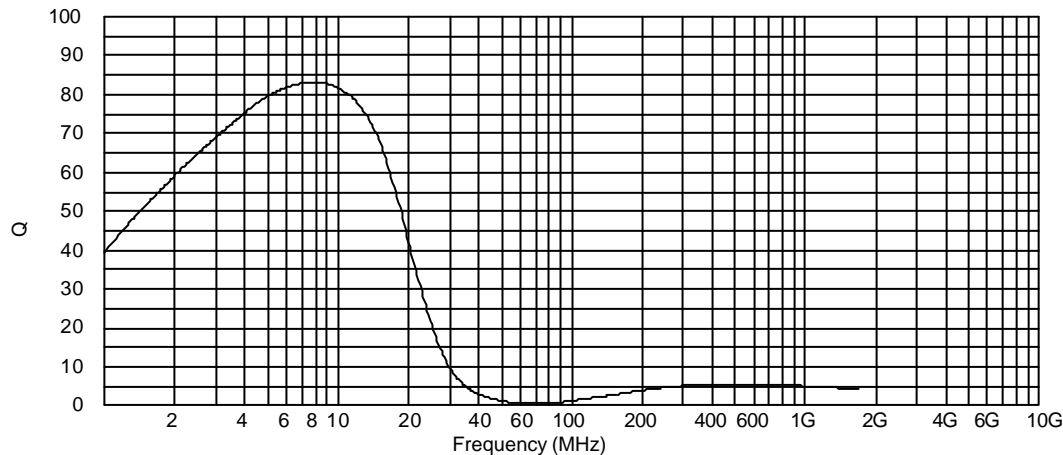
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY

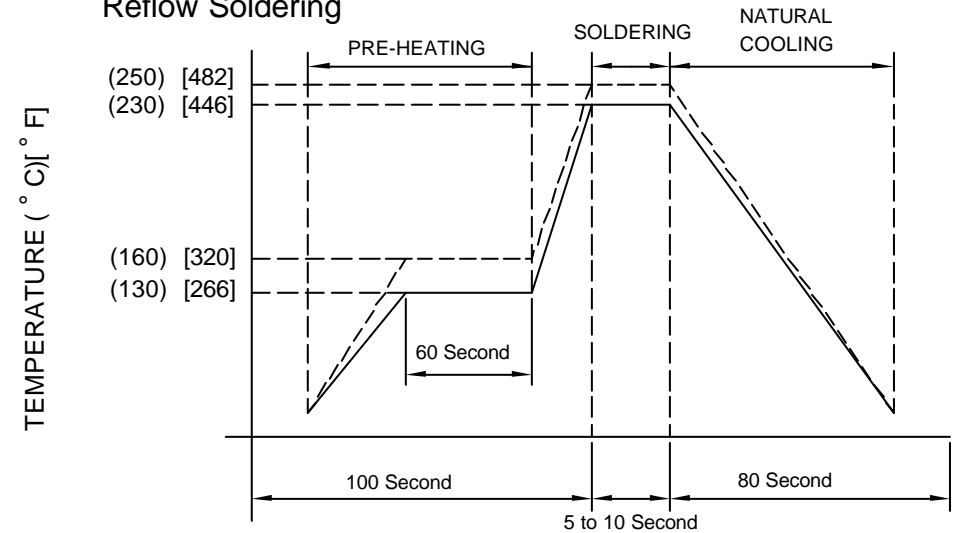


Q vs. FREQUENCY CHARACTERISTICS



RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

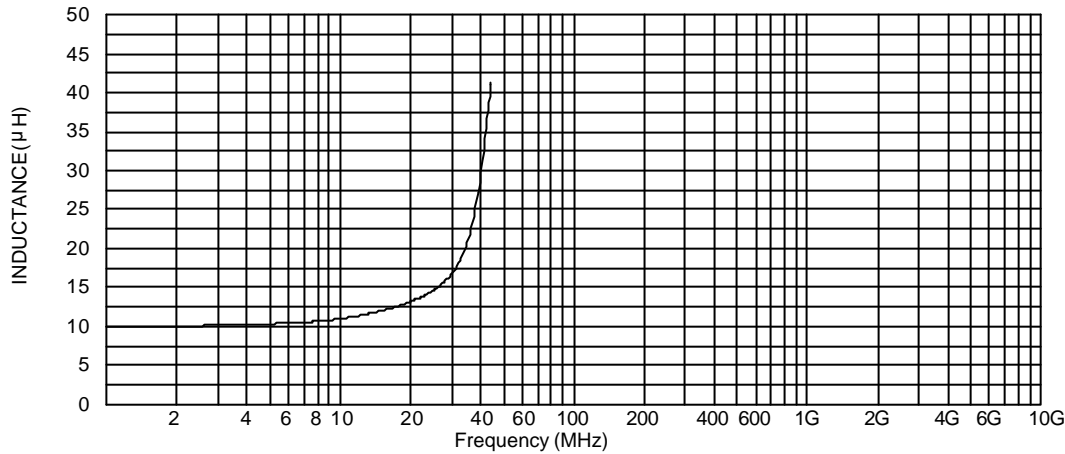
For lead free solder - - - - -

BCCL-1608E1-10RK

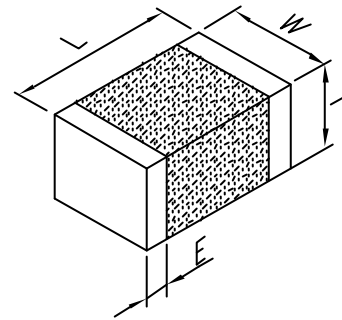
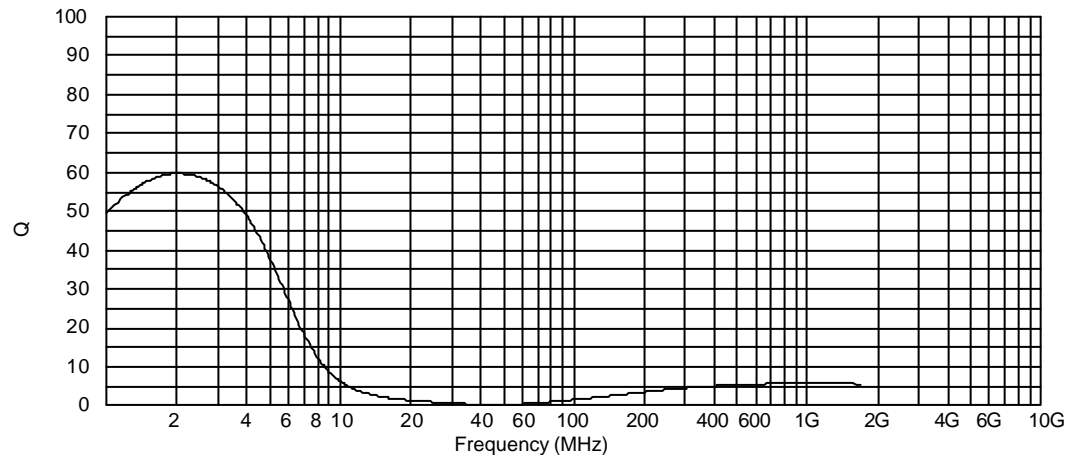
ELECTRICAL CHARACTERISTICS:

L@2MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
10	30	1.85	17	3

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

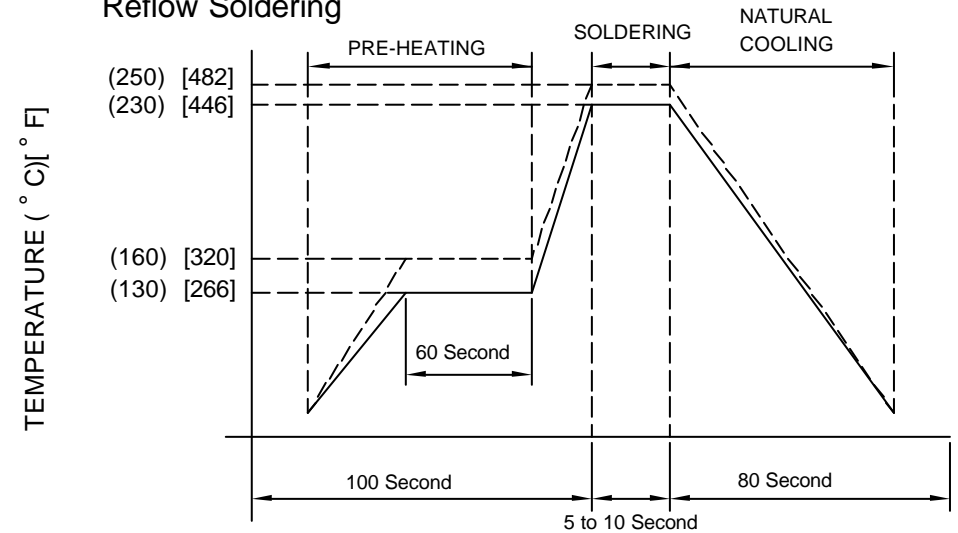
- L 1.60(0.063) ± 0.150(0.006)
- W 0.80(0.031) ± 0.150(0.006)
- T 0.80(0.031) ± 0.150(0.006)
- E 0.30(0.012) ± 0.200(0.008)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

RECOMMENDED SOLDERING CONDITIONS

Reflow Soldering



For Sn/Pb=63/37 solder _____

For lead free solder - - - - -